Compal Confidential

Model Name: V5WE2/T2/C2 (EA/EG/BA50_HW)

File Name: LA-9531P

Compal Confidential

EA50_HW M/B Schematics Document

Intel Shark Bay ULT (Hasswell + Lynx Point-LP)

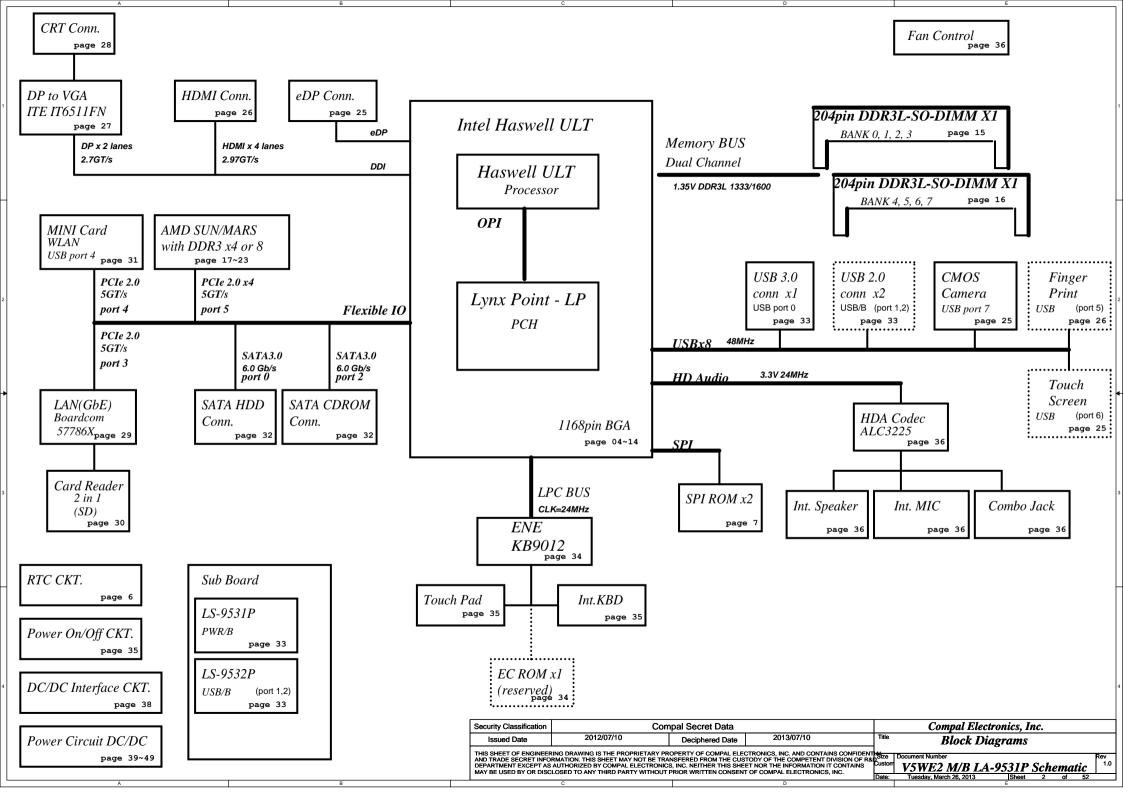
AMD MARS / SUN

2013-04-11

REV:1.0

ZZZ	
Part Number	Description
DAZ0VR00100	PCB V5WE2 LA-9531P LS-9531P/9532P
V5WE2_PCB	

Security Classification	Compal Secret Data				Compal Electronics, Inc.	
Issued Date	Issued Date 2012/07/10 Deciphered Date 2013/07/10 Title Col				Cover Page	
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Voltage Rails

Power Plane	Description	S1	S3	S5
VIN	Adapter power supply (19V)	N/A	N/A	N/A
BATT+	Battery power supply (12.6V)	N/A	N/A	N/A
B+	AC or battery power rail for power circuit.	N/A	N/A	N/A
+CPU_CORE	Core voltage for CPU	ON	OFF	OFF
+VGA_CORE	Core voltage for GPU	ON	OFF	OFF
+0.675VS	+0.675VS power rail for DDR3L terminator	ON	OFF	OFF
+1.05VS_VTT	+1.05V power rail for CPU	ON	OFF	OFF
+0.95VSDGPU	+0.95VSDGPU switched power rail for GPU	ON	OFF	OFF
+1.35V	+1.35V power rail for DDR3L	ON	ON	OFF
+1.5VS	+1.5V power rail for CPU	ON	OFF	OFF
+1.5VSDGPU	+1.5VSDGPU power rail for GPU	ON	OFF	OFF
+1.8VSDGPU	+1.8VSDGPU power rail for GPU	ON	OFF	OFF
+3VALW	+3VALW always on power rail	ON	ON	ON*
+3VLP	B+ to +3VLP power rail for suspend power	ON	ON	ON
+3VS	+3VALW to +3VS power rail	ON	OFF	OFF
+3VSDGPU	+3VS to +3VSDGPU power rail for GPU	ON	OFF	OFF
+5VALW	+5VALWP to +5VALW power rail	ON	ON	ON*
+5VS	+3VALW to +5VS power rail	ON	OFF	OFF
+RTCVCC	RTC power	ON	ON	ON
Note : ON* means	s that this power plane is ON only with AC power available	e, otherwise it is	OFF.	

EC SM Bus1 address

EC SM Bus2 address

Device	Address	Device	Address
Smart Battery	0001 011X	On Board Thermal Senser	0100 110x
		VGA Internal Thermal Senser	0100 000x
		G Senser	0011 000x

PCH SM Bus address

Device		Address	
ChannelA	DIMM0	1001 000x	JDIMM1
ChannelB	DIMM1	1001 010x	JDIMM2

_								
STATE	SLP_S1#	SLP_S3#	SLP_S4#	SLP_S5#	+VALW	+V	+VS	Clock
Full ON	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON
S1(Power On Suspend)	LOW	HIGH	HIGH	HIGH	ON	ON	ON	LOW
S3 (Suspend to RAM)	LOW	LOW	HIGH	HIGH	ON	ON	OFF	OFF
S4 (Suspend to Disk)	LOW	LOW	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF

Board ID / SKU ID Table for AD channel

Vcc	3.3V +/- 5%			
Ra/Rc/Re	100K +/- 5%			
Board ID	Rb / Rd / Rf	Vad_BID min	Vad_BID typ	Vad_bid max
0	0	0 V	0 V	0 V
1	8.2K +/- 5%	0.216 V	0.250 V	0.289 V
2	18K +/- 5%	0.436 V	0.503 V	0.538 V
3	33K +/- 5%	0.712 V	0.819 V	0.875 V
4	56K +/- 5%	1.036 V	1.185 V	1.264 V
5	100K +/- 5%	1.453 V	1.650 V	1.759 V
6	200K +/- 5%	1.935 V	2.200 V	2.341 V
7	NC	2.500 V	3.300 V	3.300 V

BOARD ID Table

Board ID	PCB Revision
0	0.1
1	0.2
2	0.3
3	0.4
4	0.5
5	1.0
6	
7	

USB Port Table

USB 2.0	Port	3 External USB Port			
	0	USB Port(Left 3.0)			
	1	USB Port(Right 2.0)			
	2	USB Port(Right 2.0)			
EHCI1	3				
Encii	4	Mini Card (WLAN+BT)			
	5				
	6				
	7	Camera			

Unpop	@			
Connector	CONN@			
EC 932	940@			
EC 9012	9012@			
UMA Component	UMA@			
AMD GPU	VGA@			
1 SPI ROM	1ROM@			
2 SPI ROM	2ROM@			
Assembly Level	45 @			
Cable for Power	45PWR@			
KB Backlight	BL@			
Debug Only	DEG@			
EMC Component	EMC@			
Reservec for EMC	XEMC@			
eDP to LVDS	TL@			
TPM Module	TPM@			
G-Sensor	GSEN@			
V5WE2/T2/C2	EA50@			
Reserved	BA51@			
Touch Screen	TS@			
For IOAC	IOAC@			
For EDP panel	EDP@			
Mars component	MARS@			
SUN component	SUN@			
VRAM x 8pcs	128@			
VRAM Selection	x76 @			
Micron 4G x 8	X7601@			
Hynix 2G x 4	X7603@			
Hynix 2G x 8	X7604@			

BTO Option Table

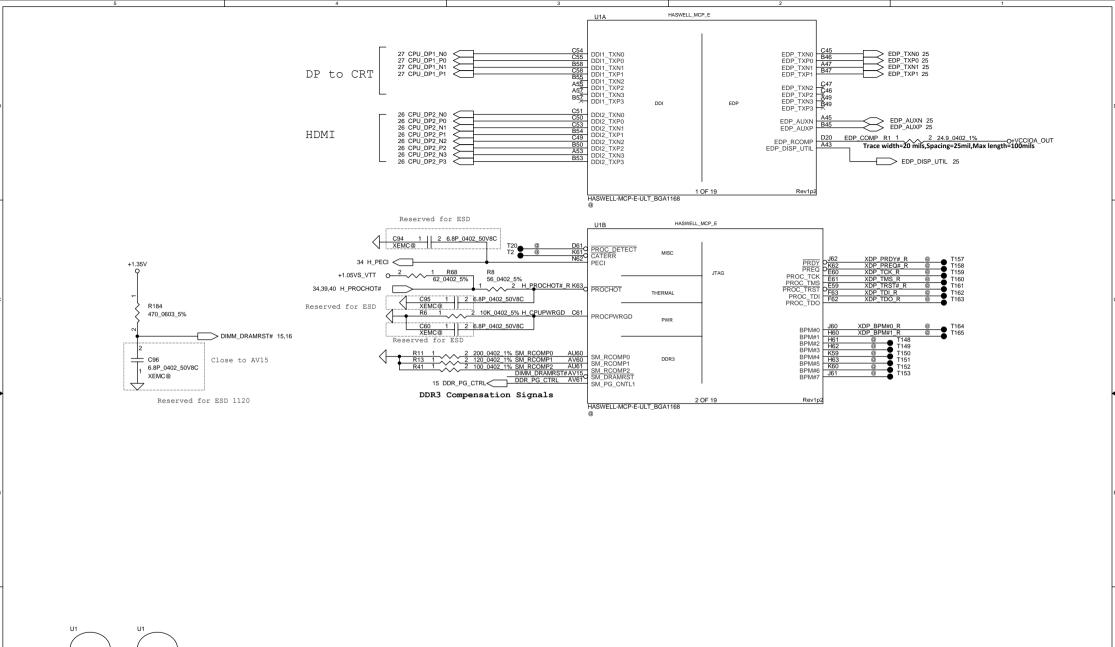
BOM Structure

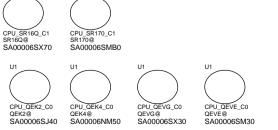
BTO Item

	USB 3.0	Port	
	XHCI	0	USB Port(Left 3.0)
		1	
		2	
		3	

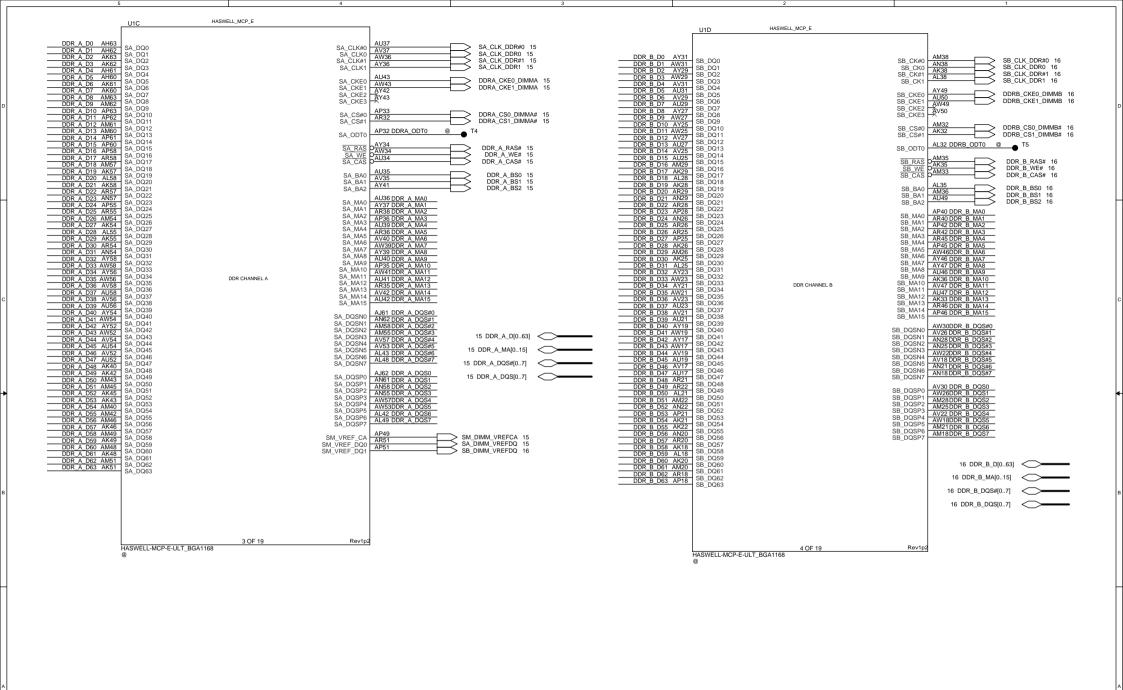
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Thursday, April 11, 2013 | Sheet 3 of 52

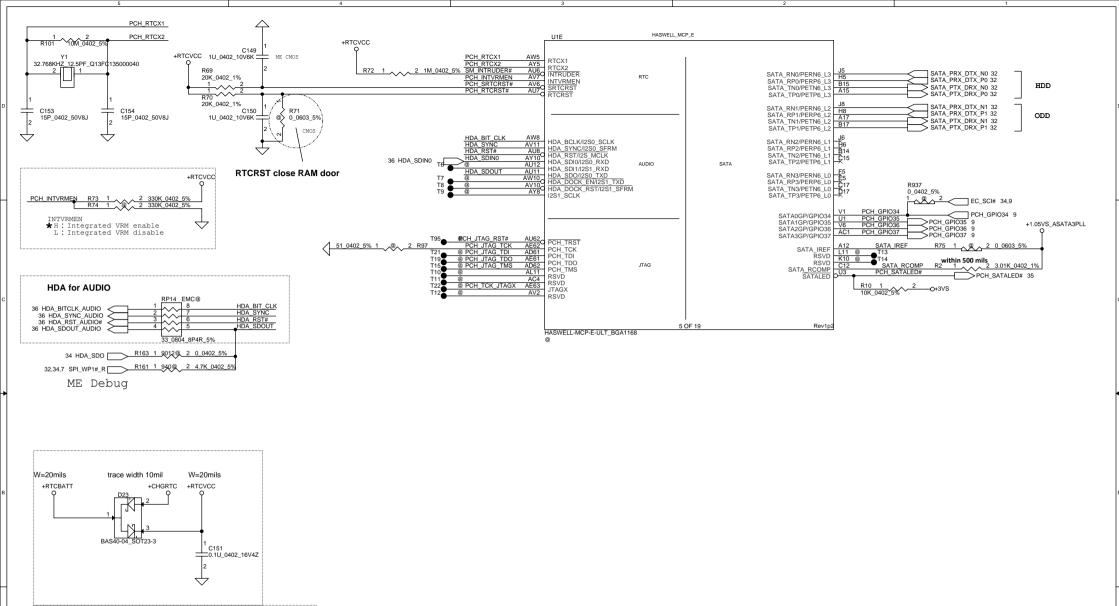


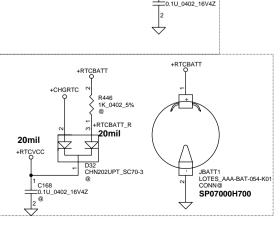


Security Classification	0040/07/40				Compal Electronics, Inc.
Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	HSW MCP(1/11) DDI,MSIC,XDP
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			·	Date:	: Monday, April 08, 2013 Sheet 4 of 52

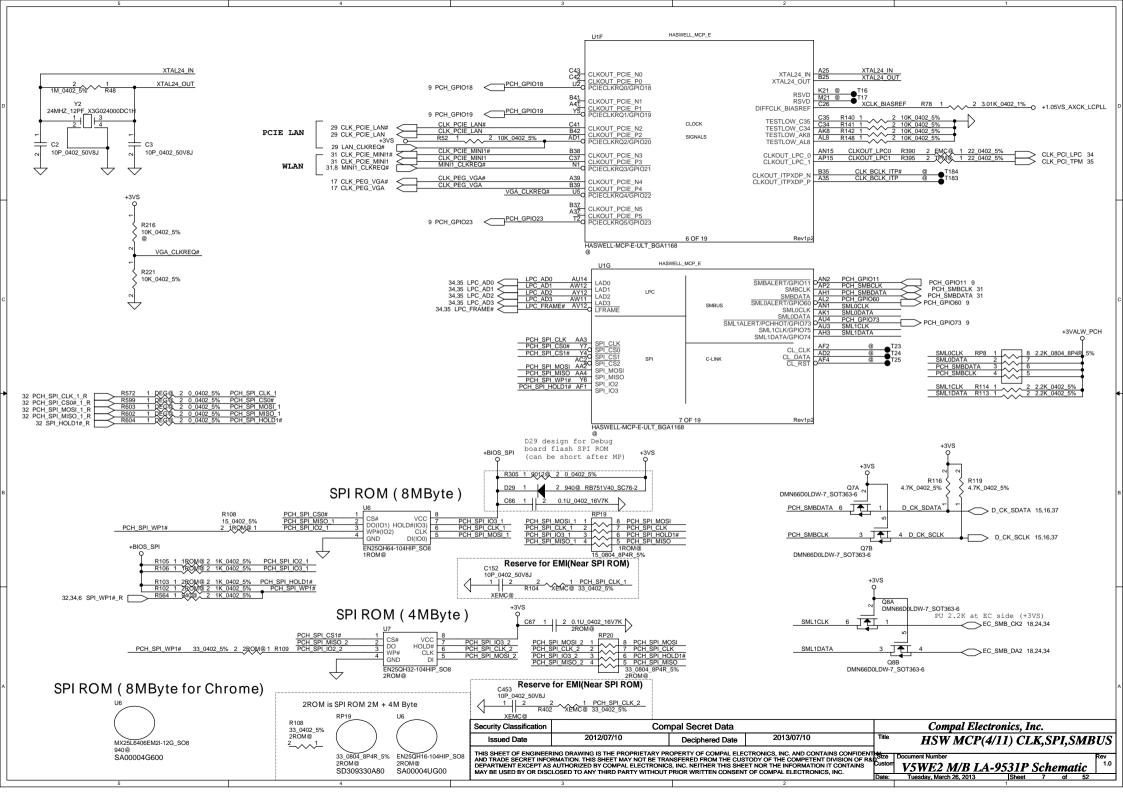


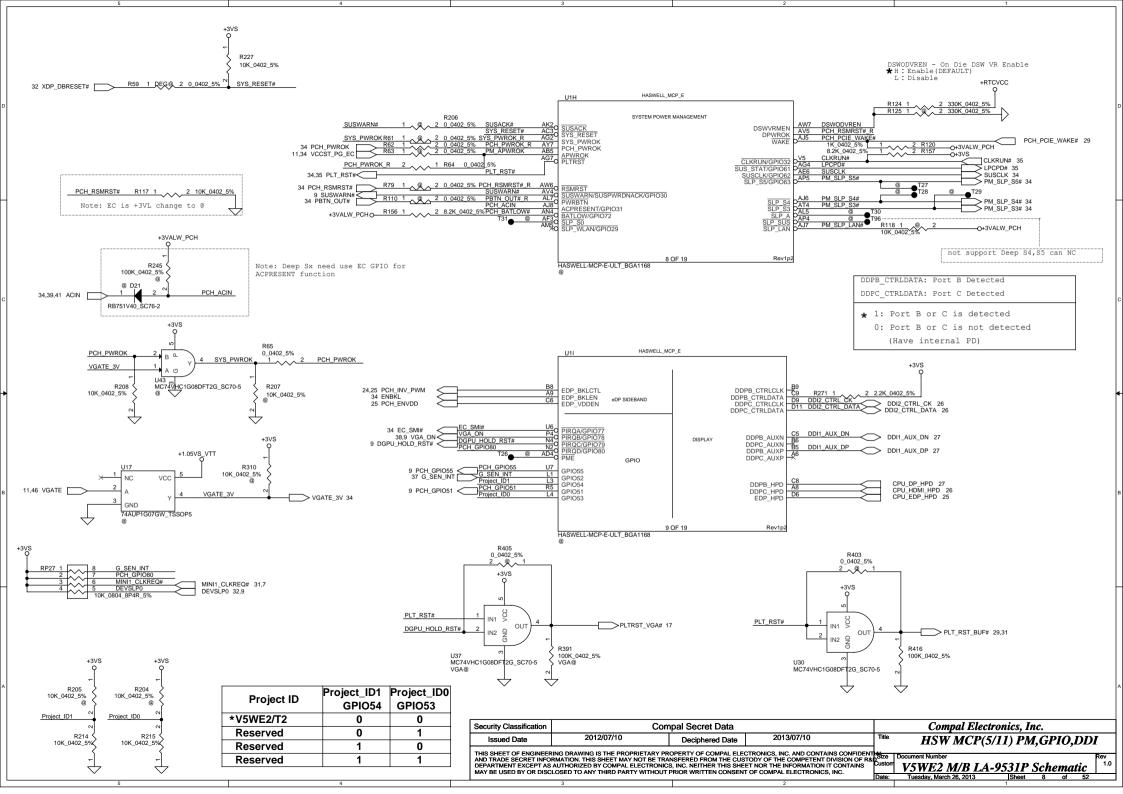
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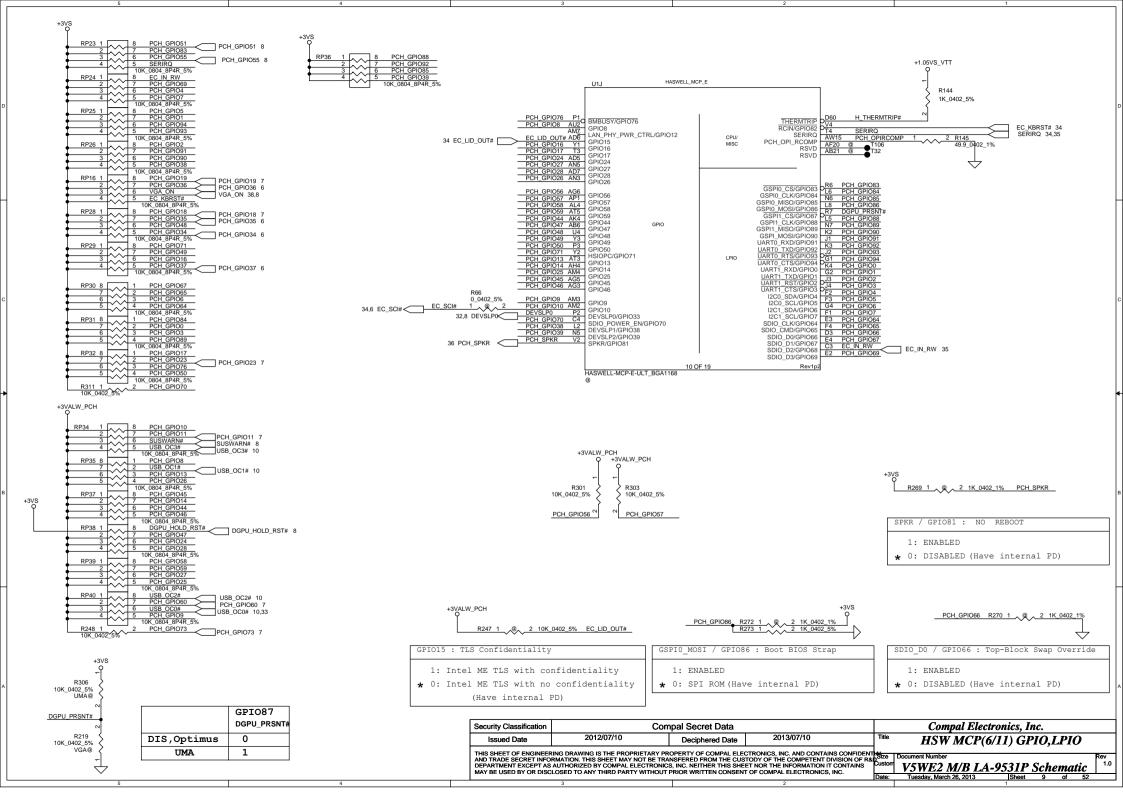


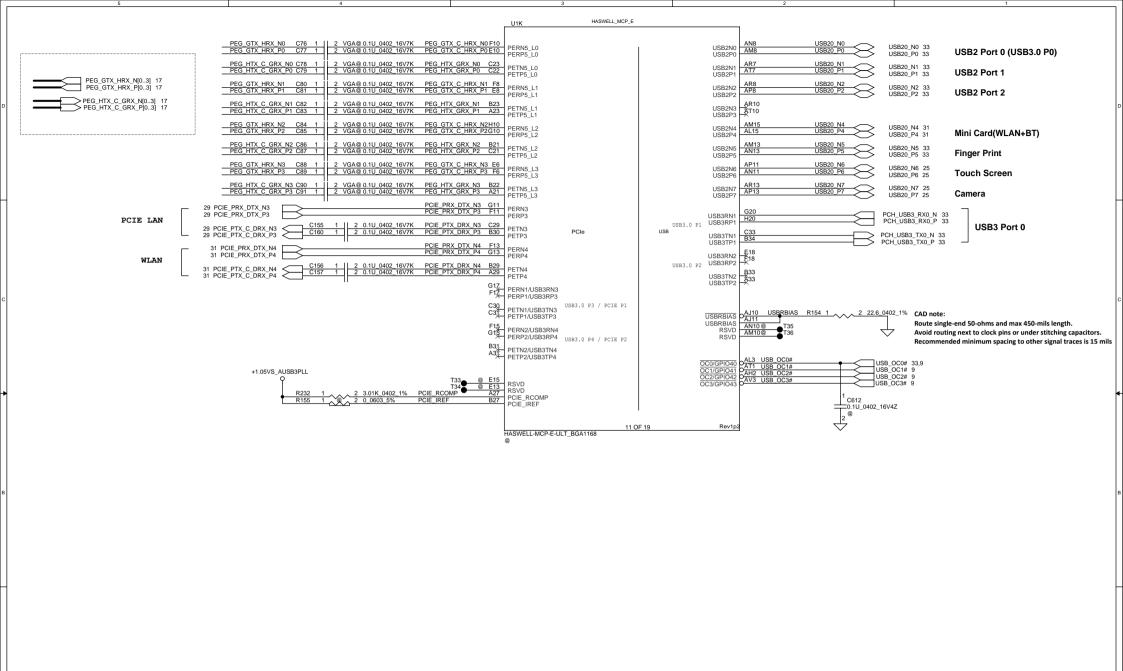


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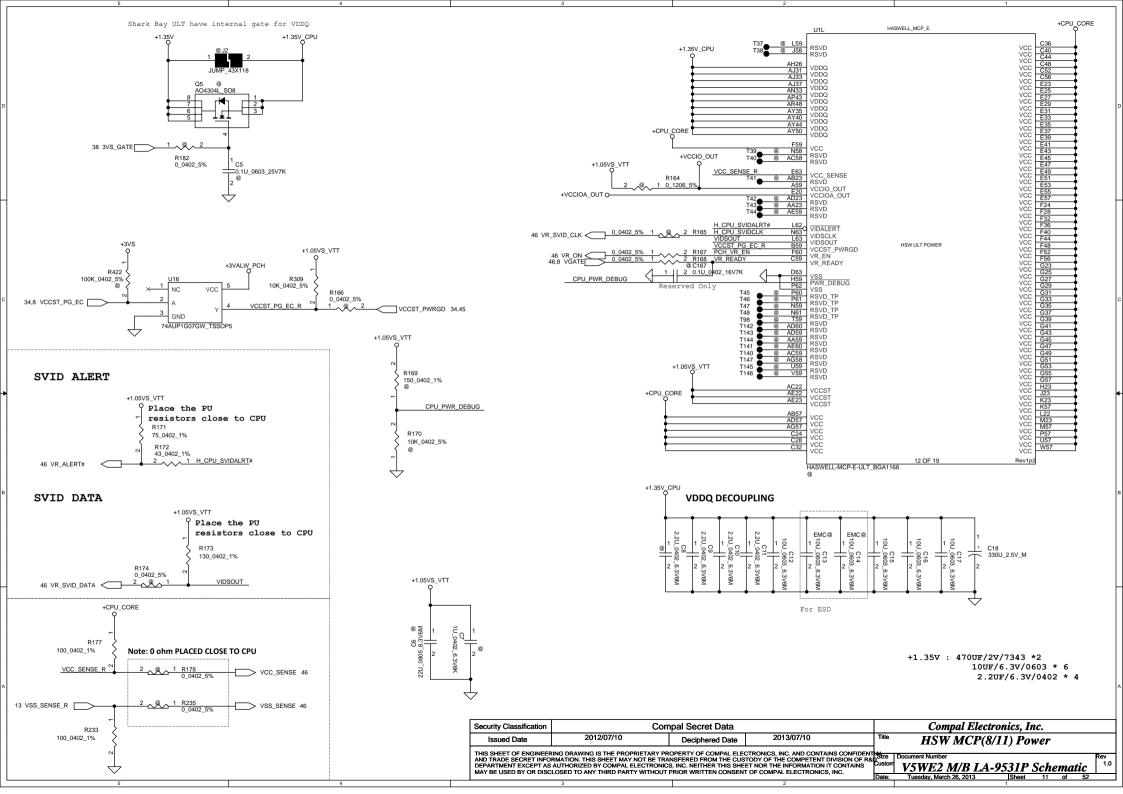


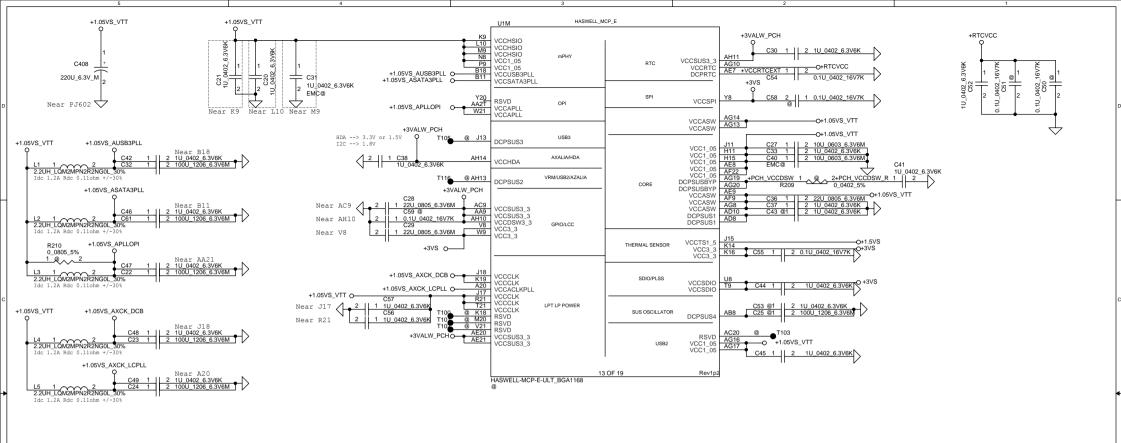




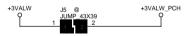


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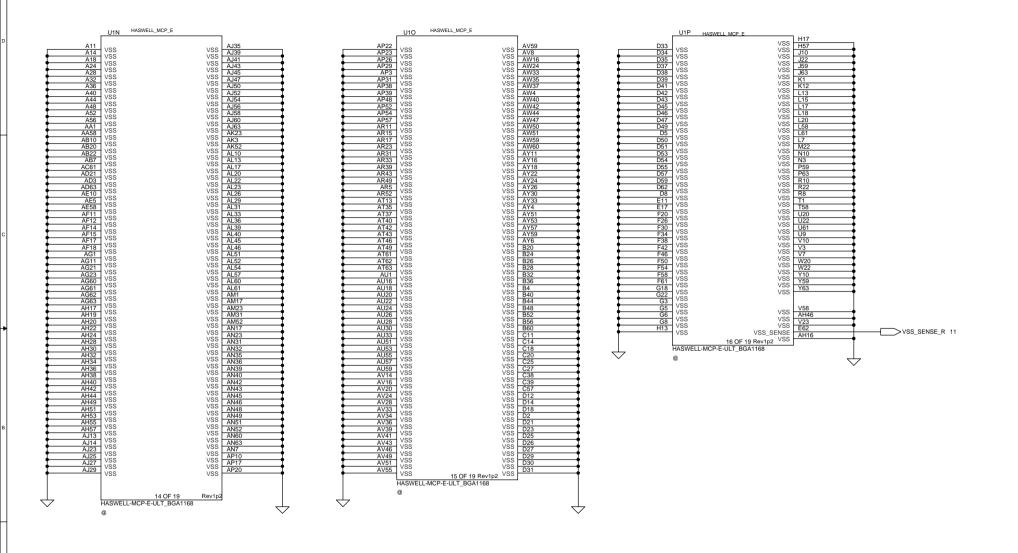








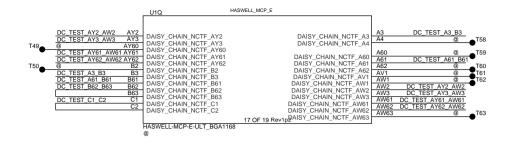
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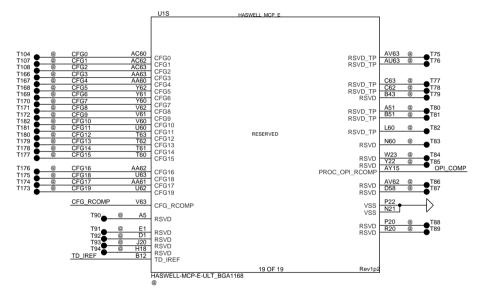


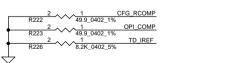
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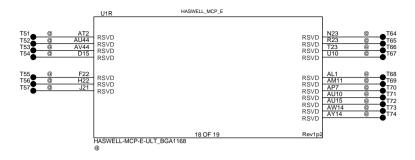
Date: Tuesday, March 26, 2013

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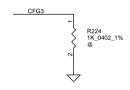




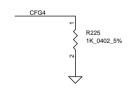




CFG Straps for Processor

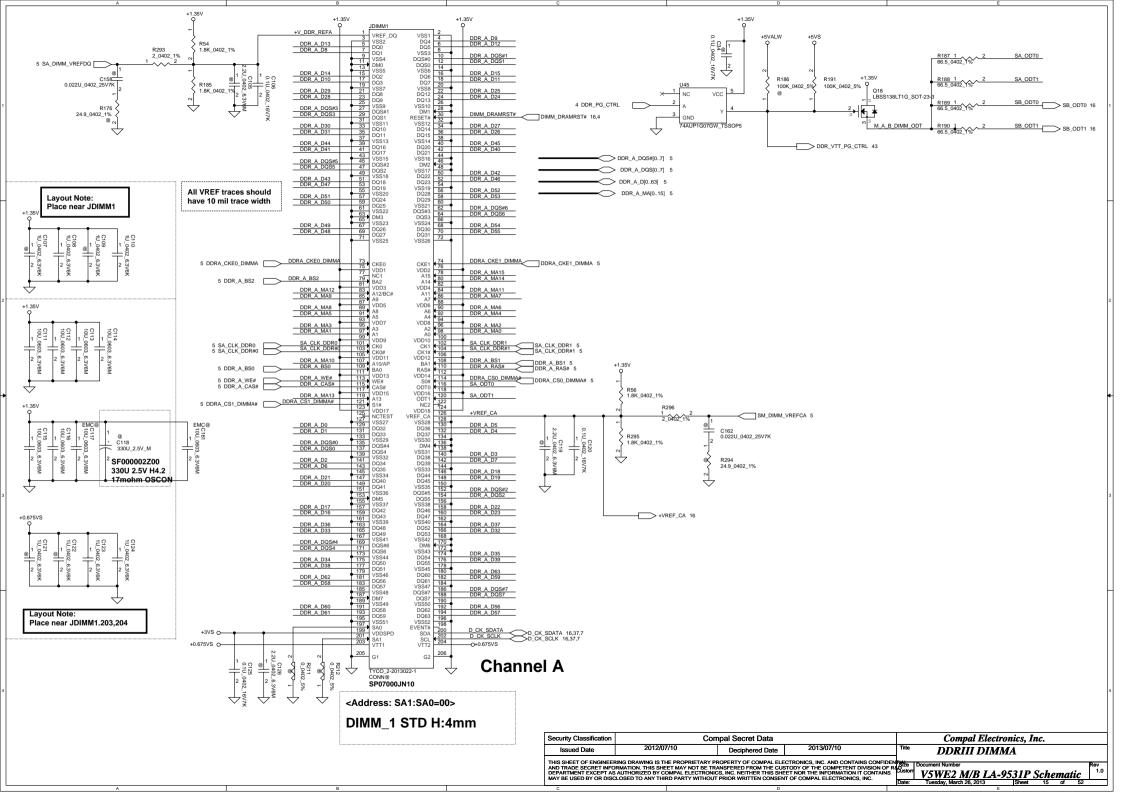


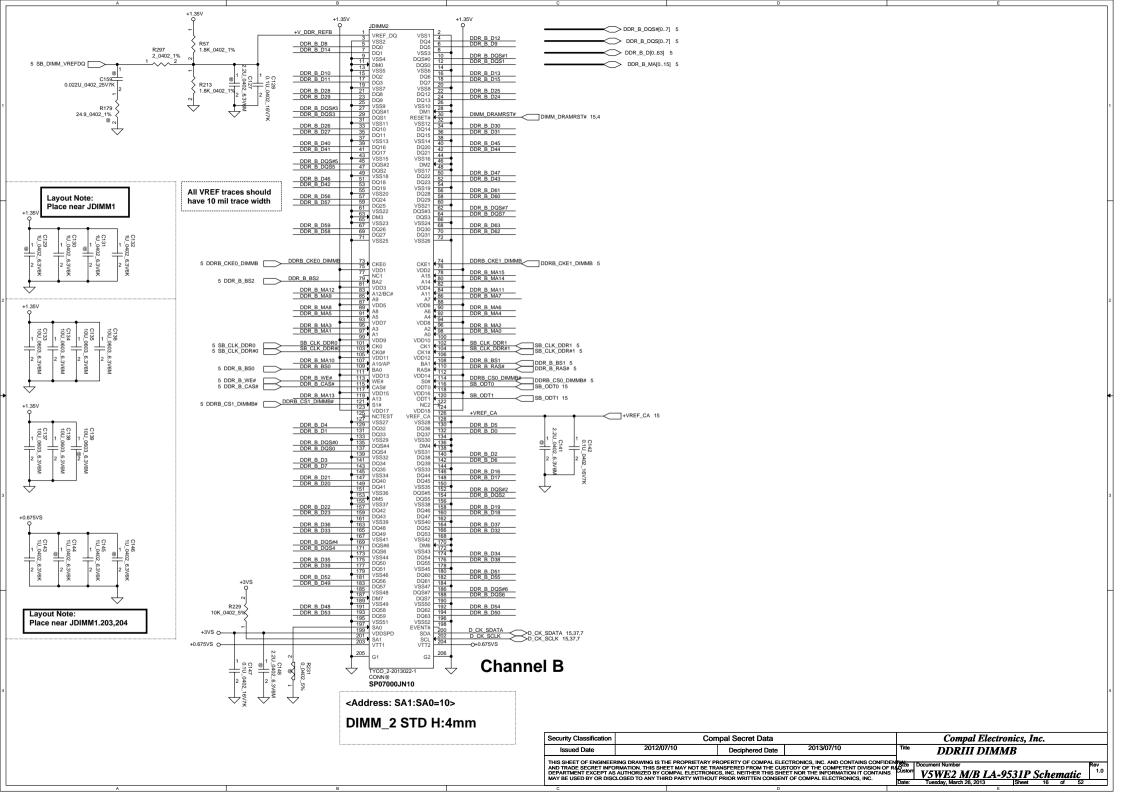


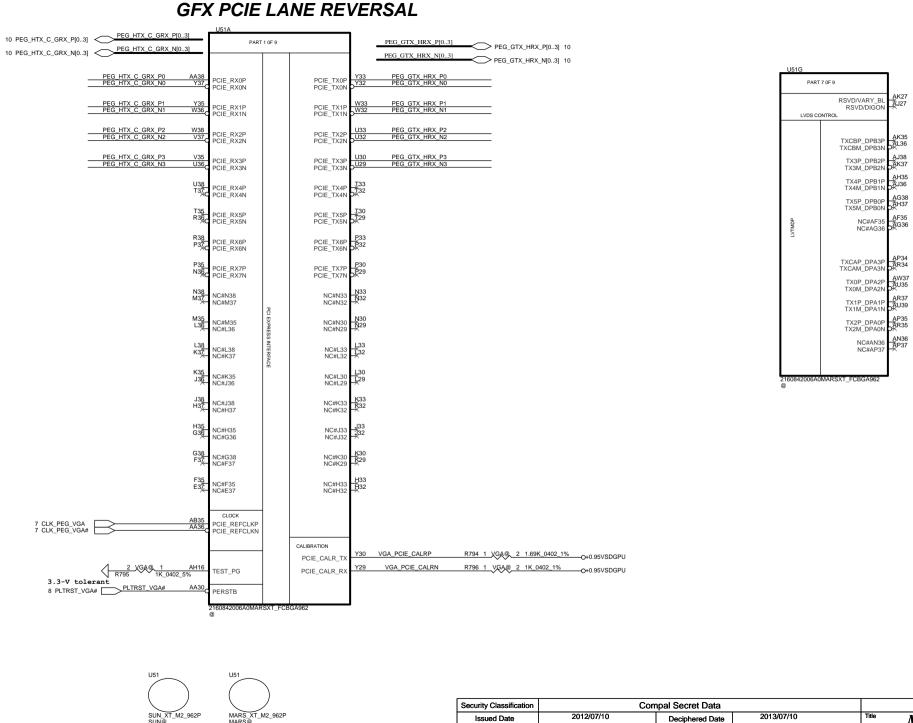


Display	Display Port Presence Strap					
CFG4	1 : Disabled; No Physical Display Port attached to Embedded Display Port					
	0 : Enabled; An external Display Port device is connected to the Embedded Display Port					

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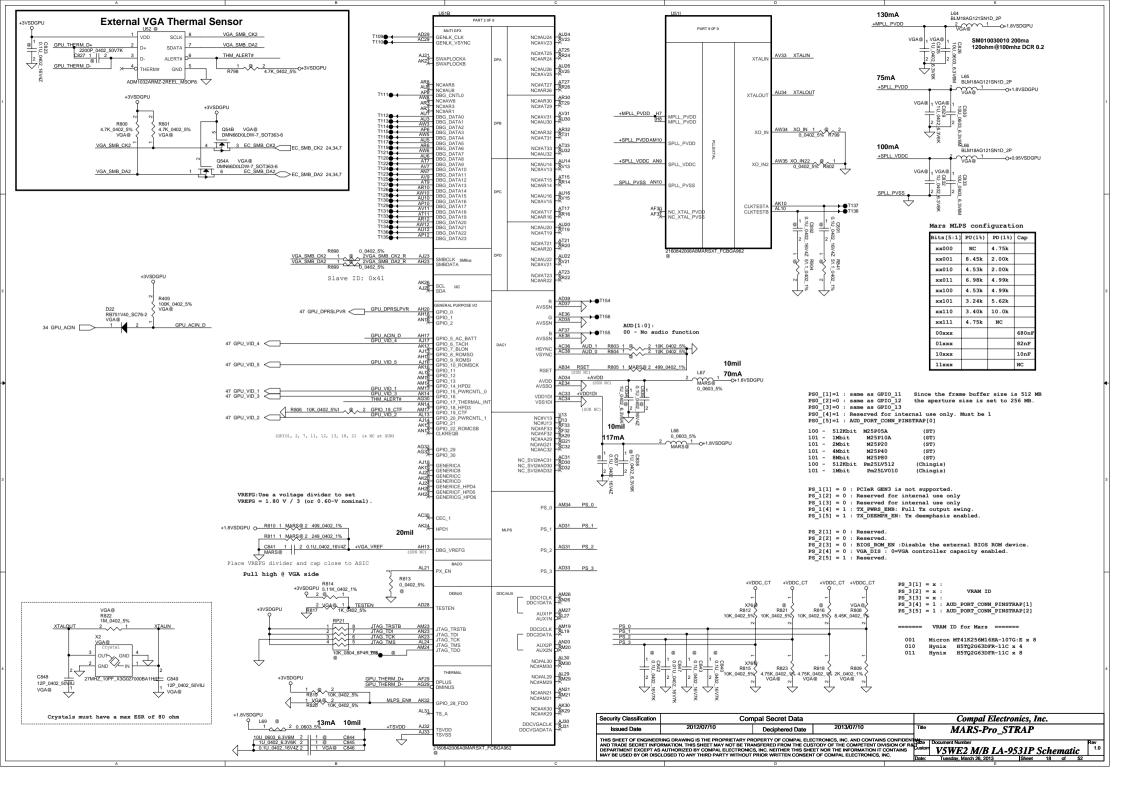
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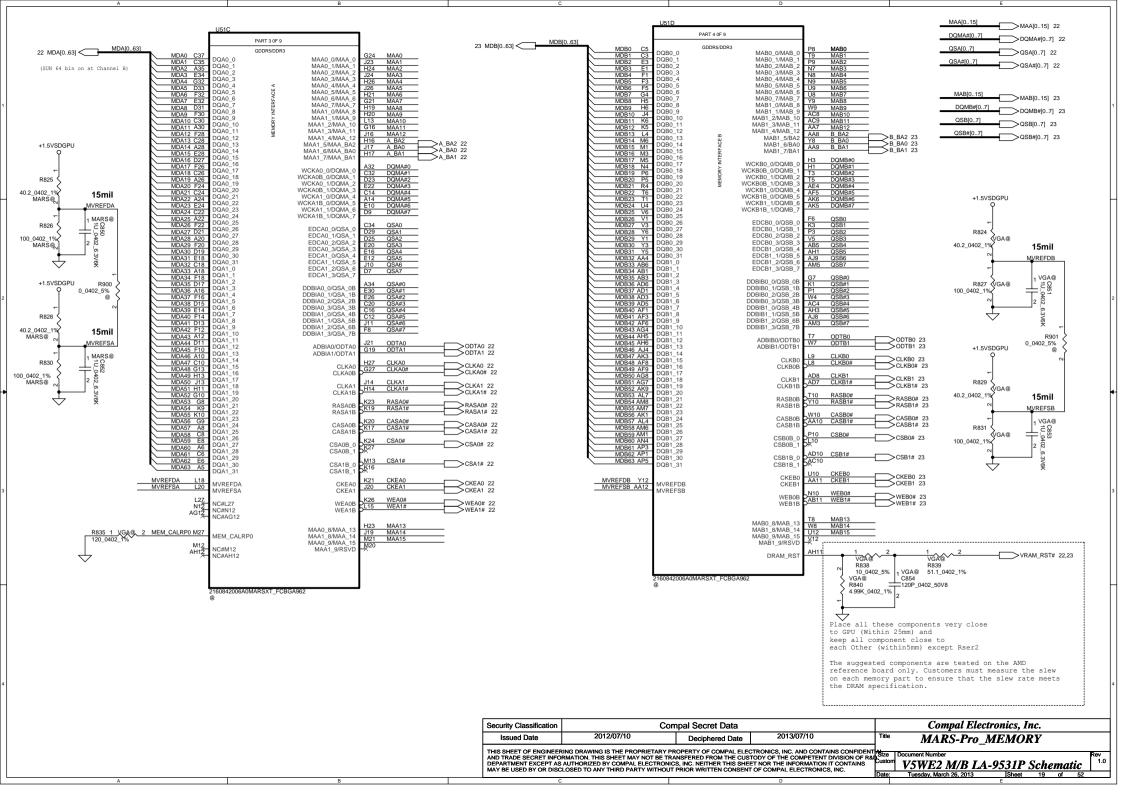
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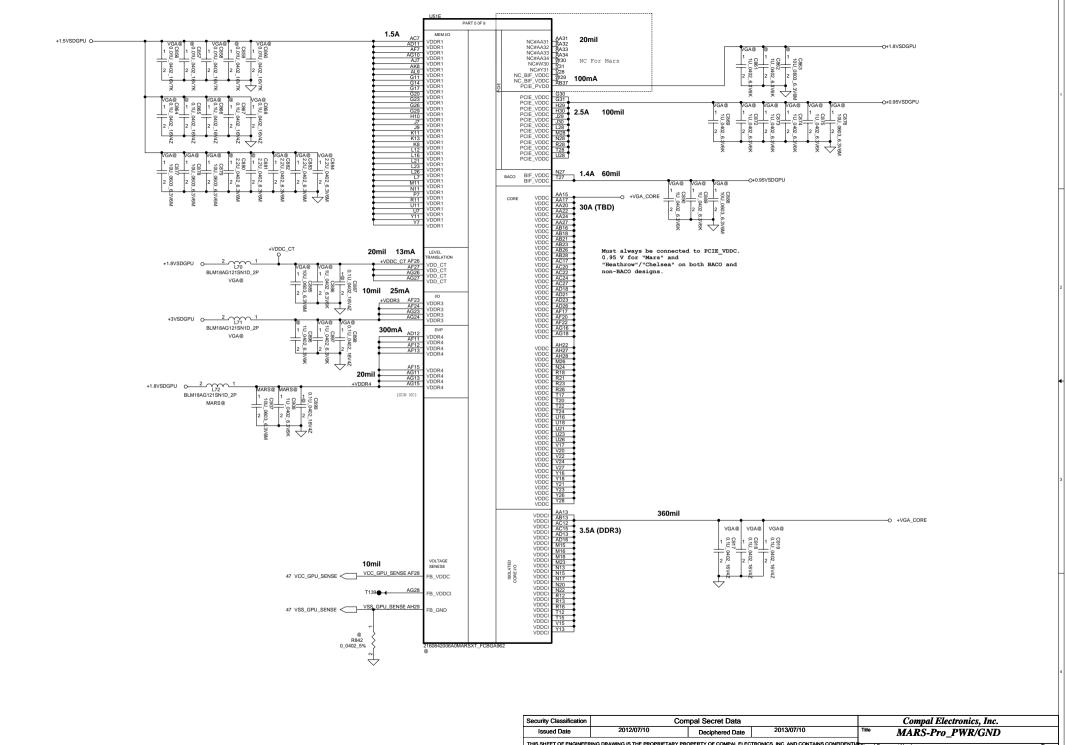
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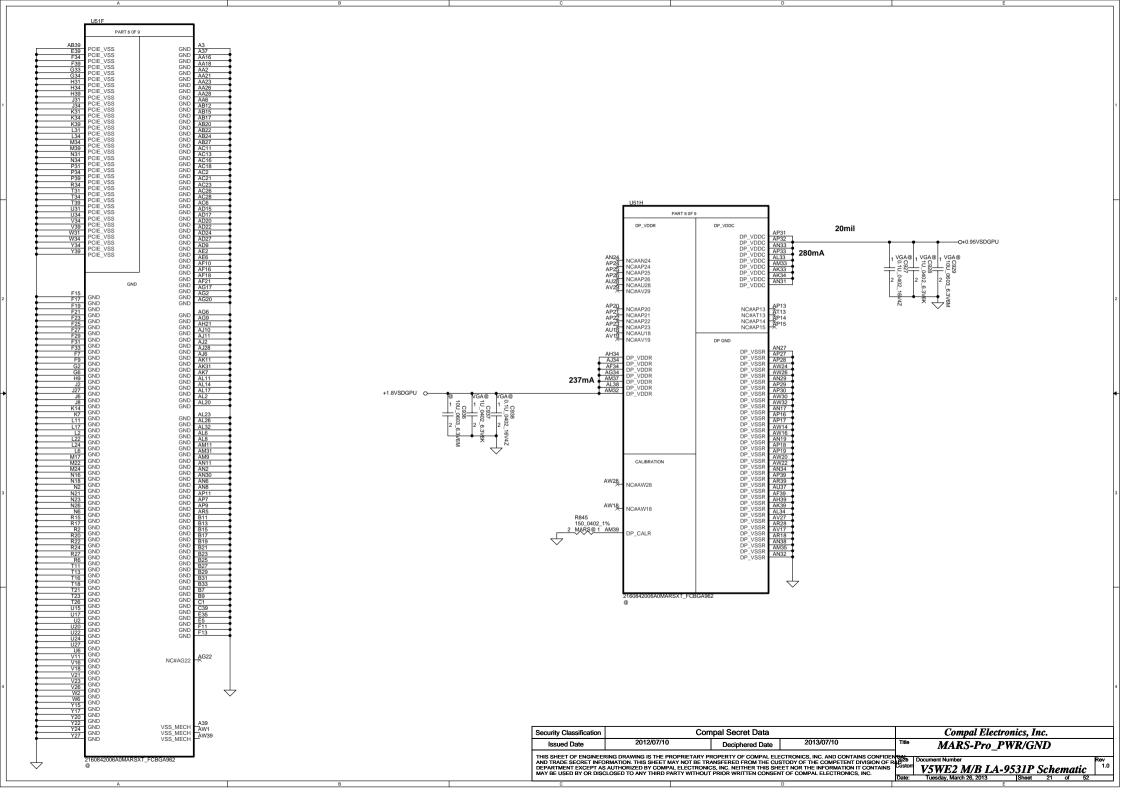
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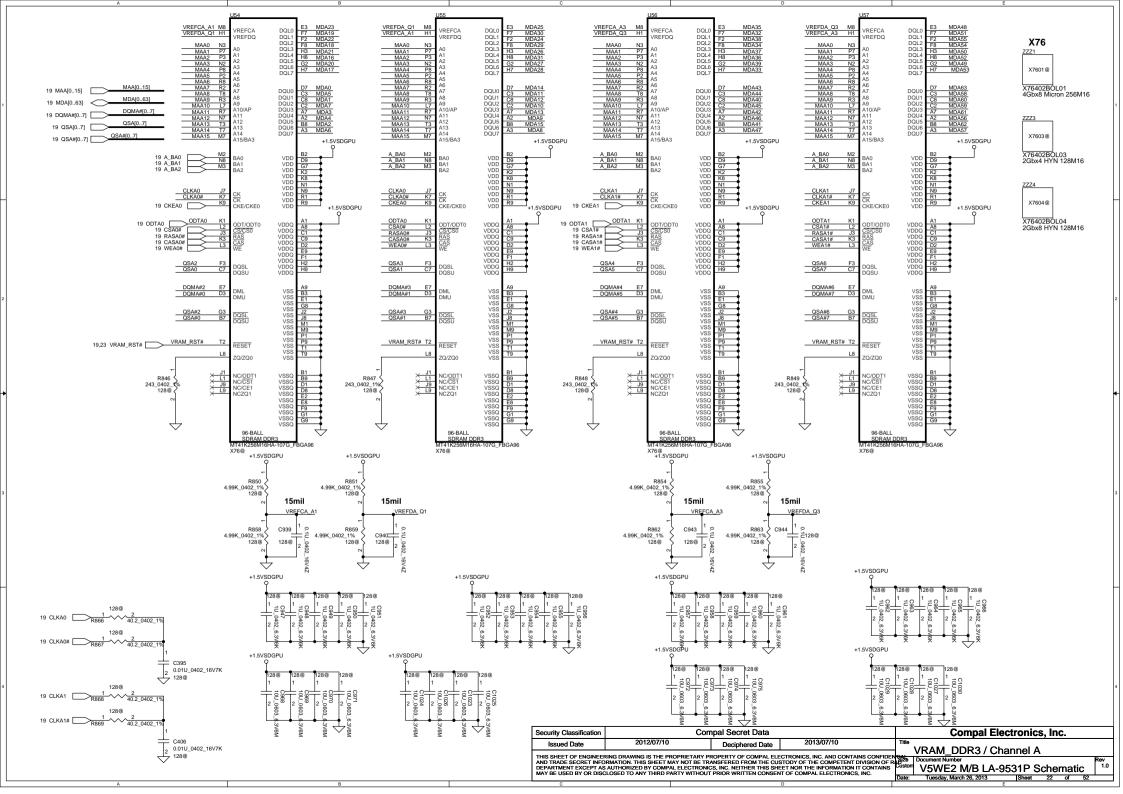


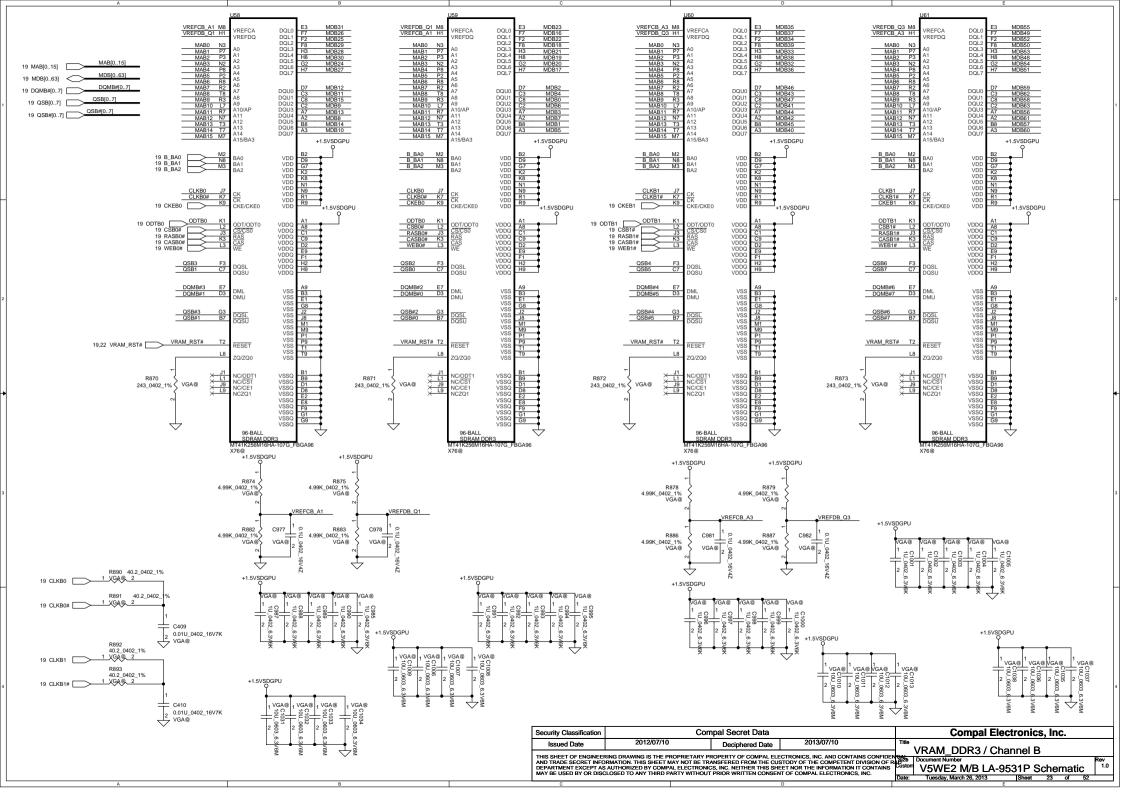


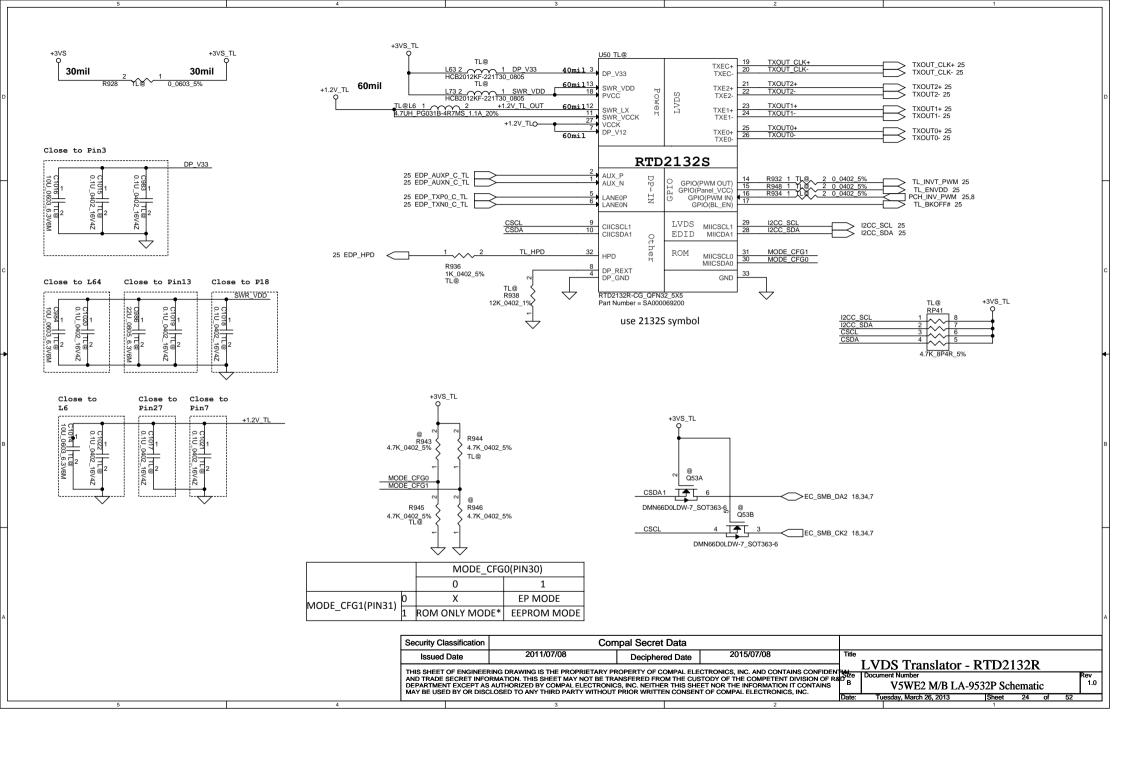


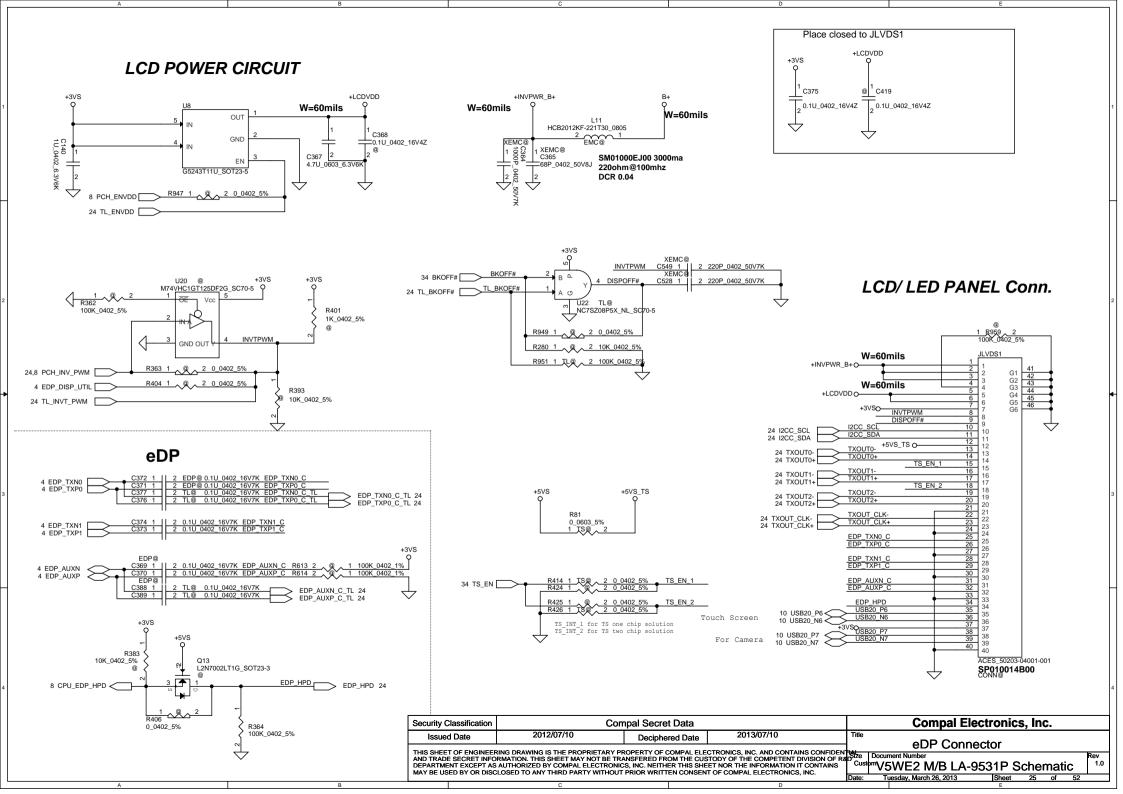
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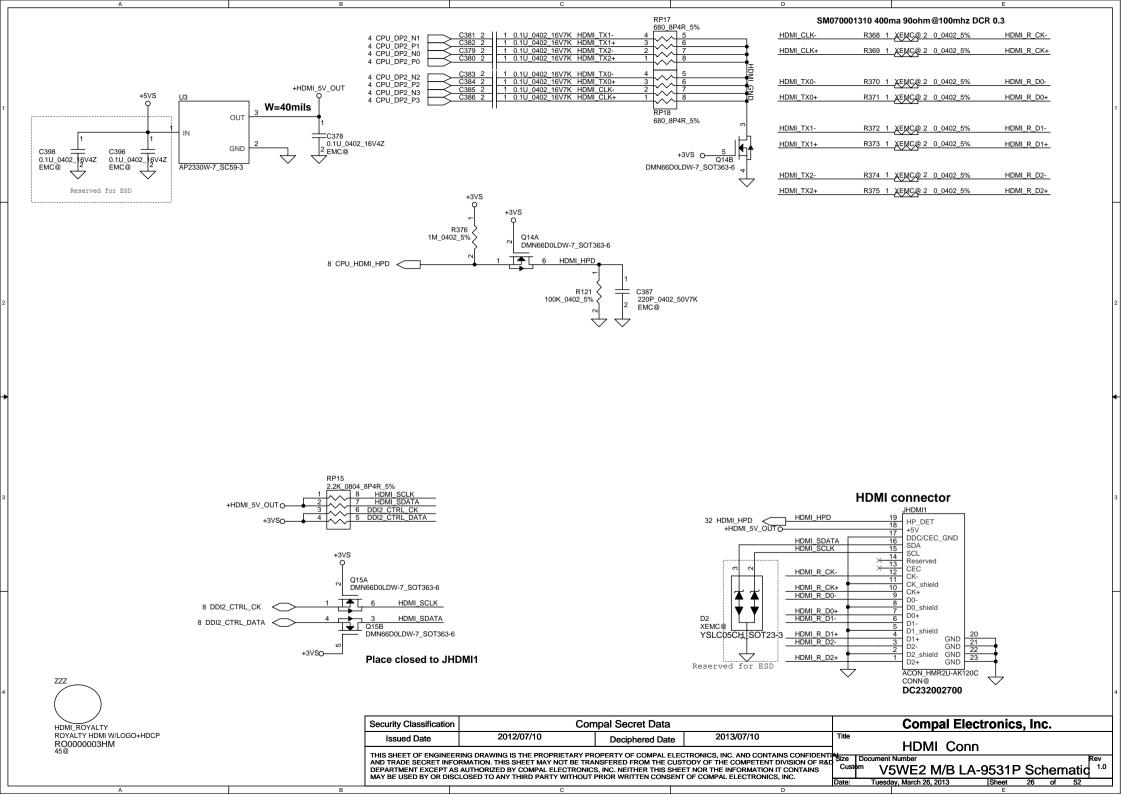


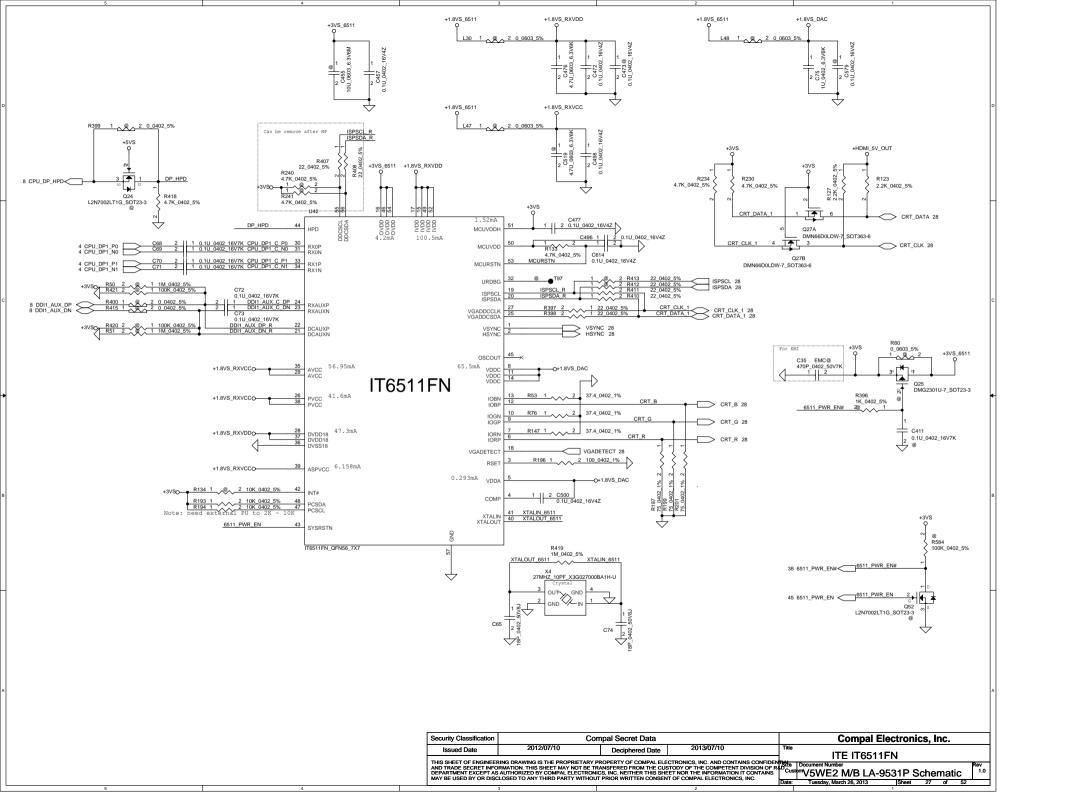


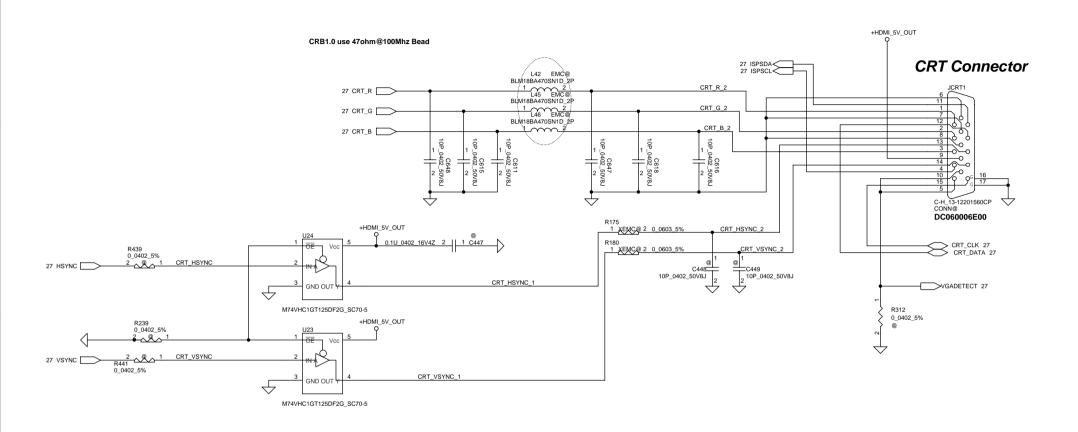


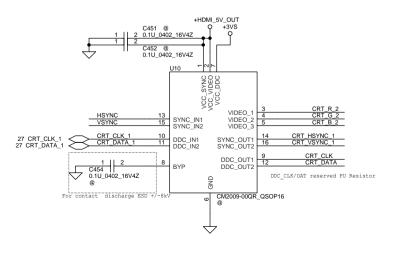




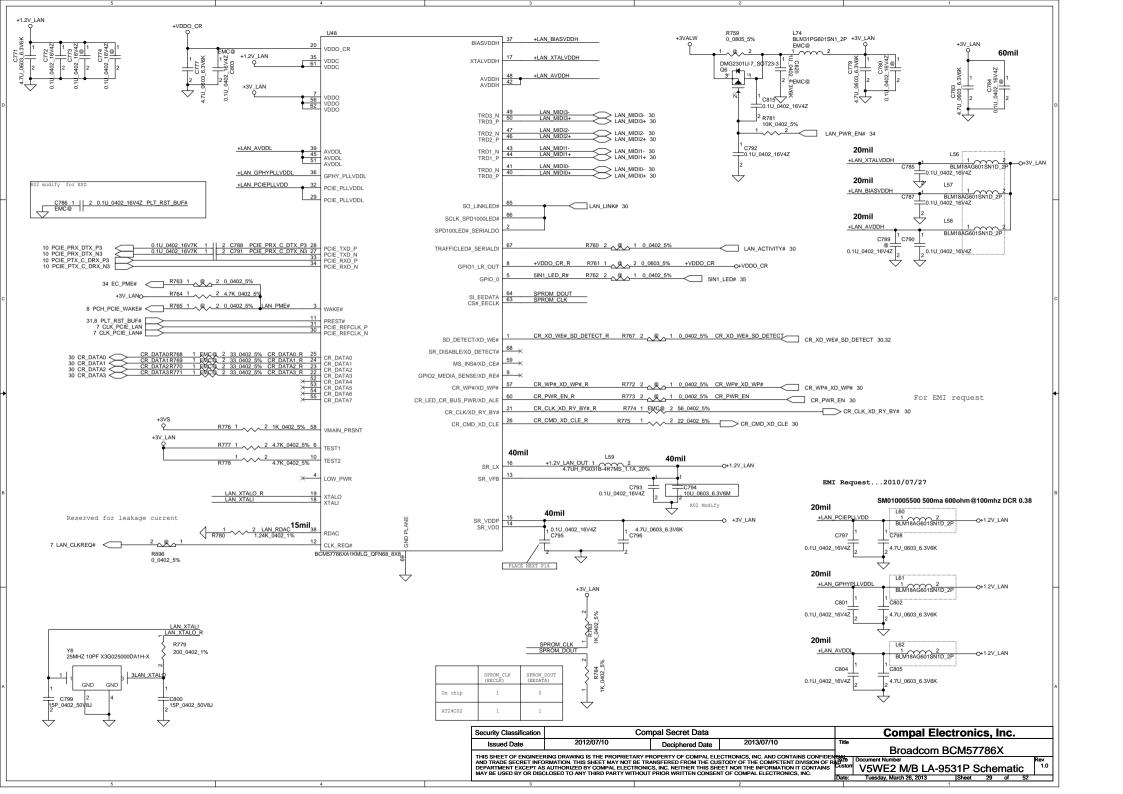


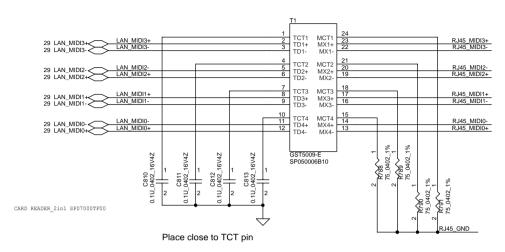






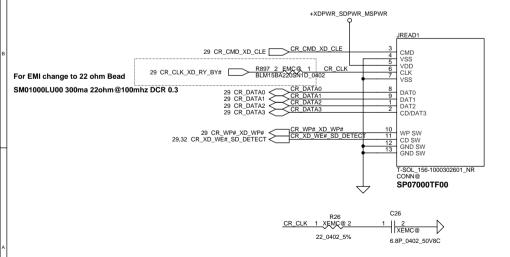
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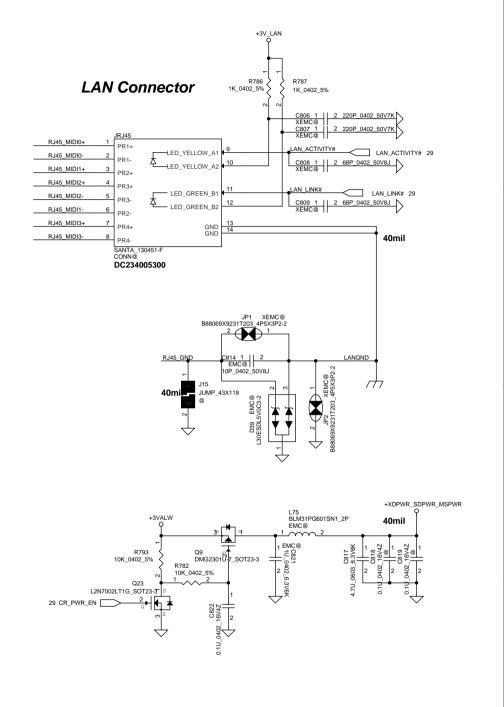




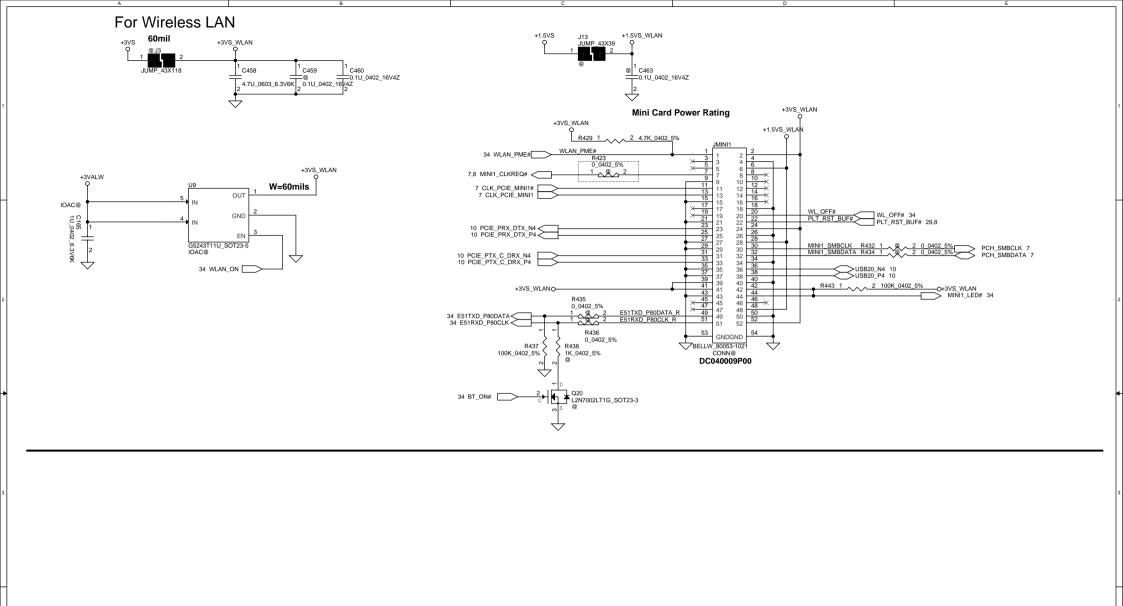
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Card Reader Connector

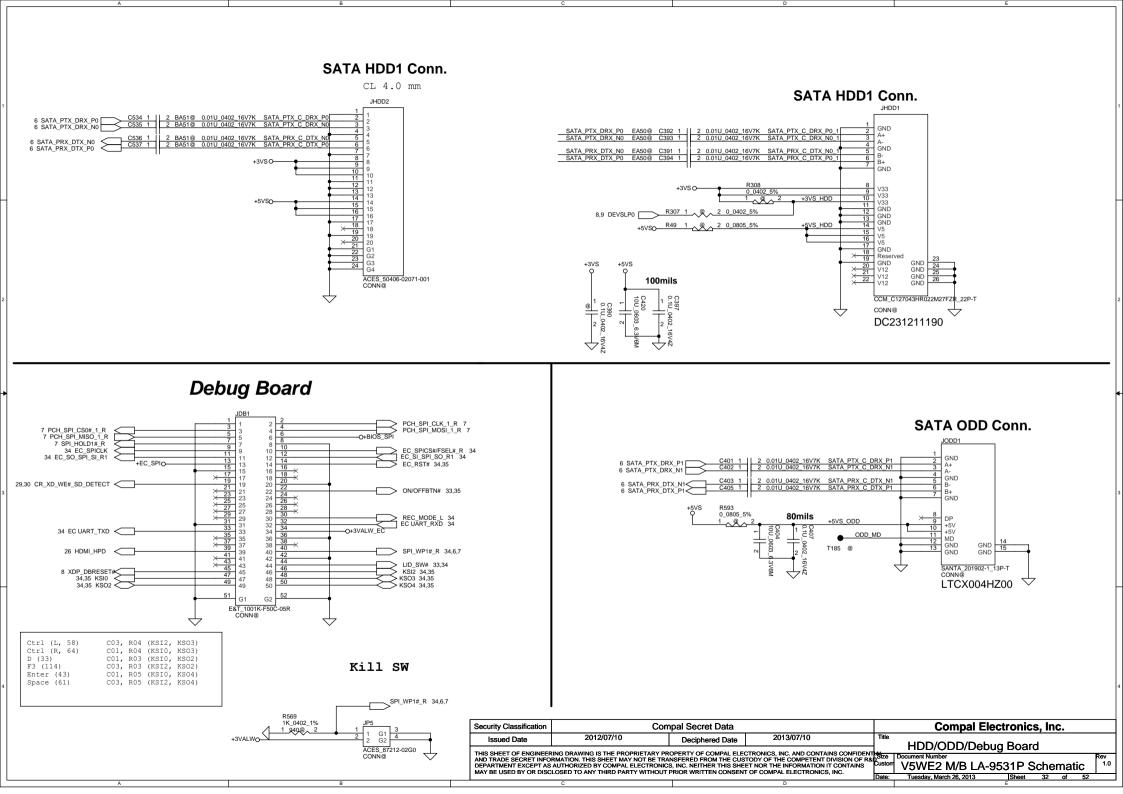


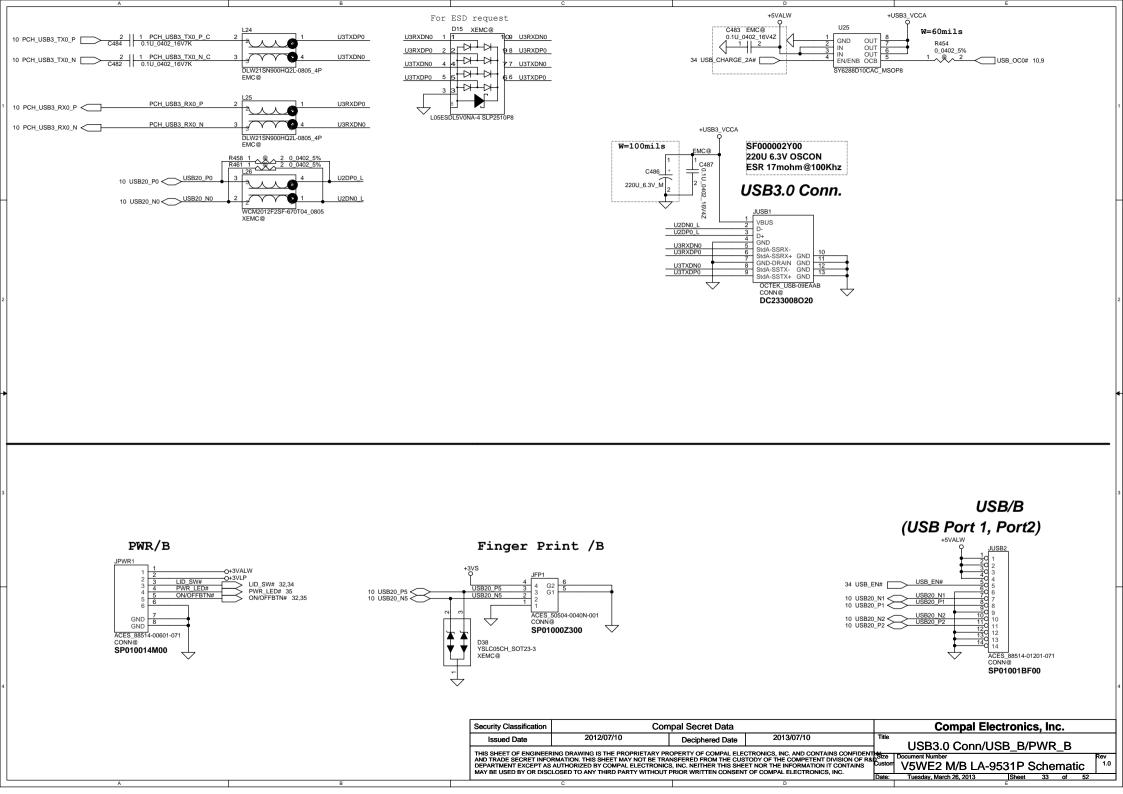


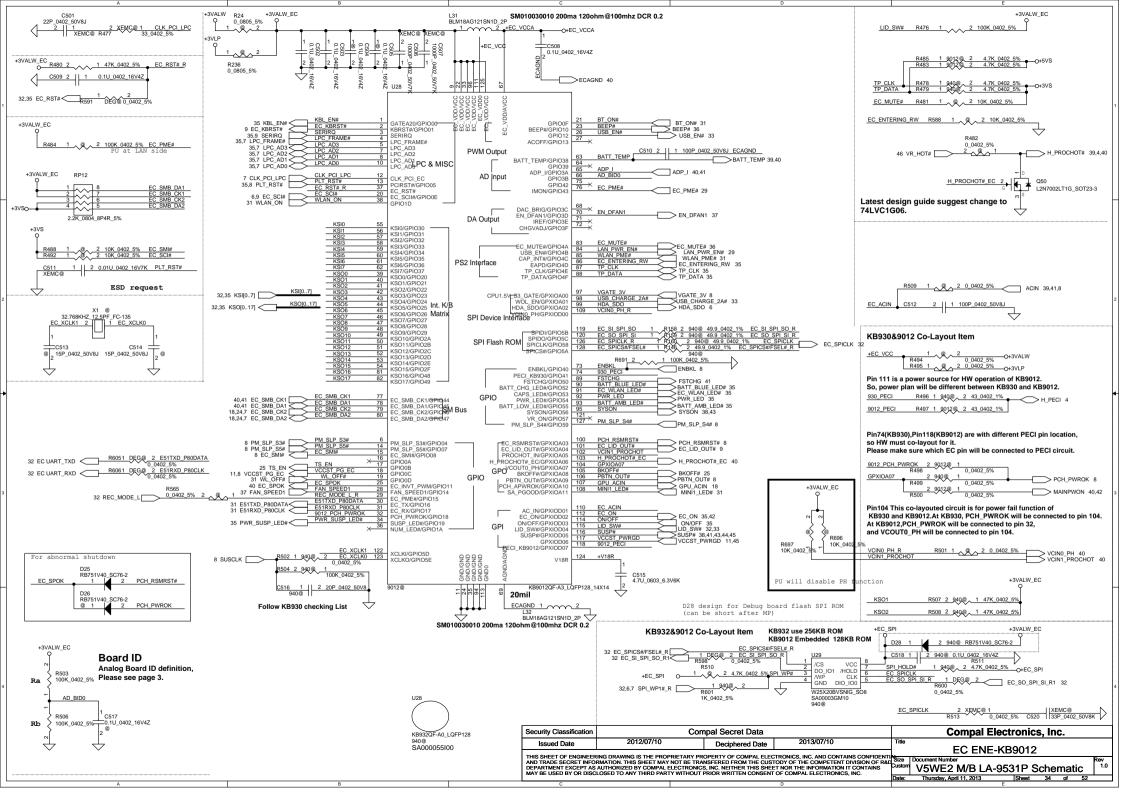
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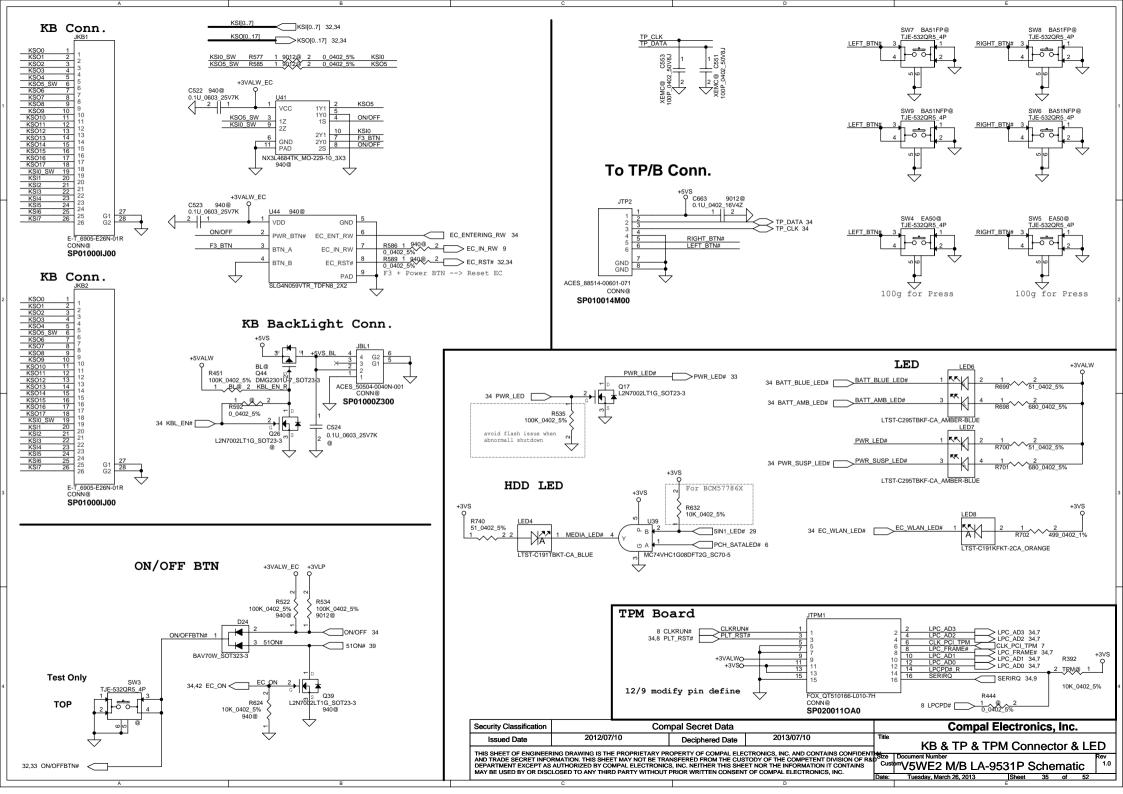


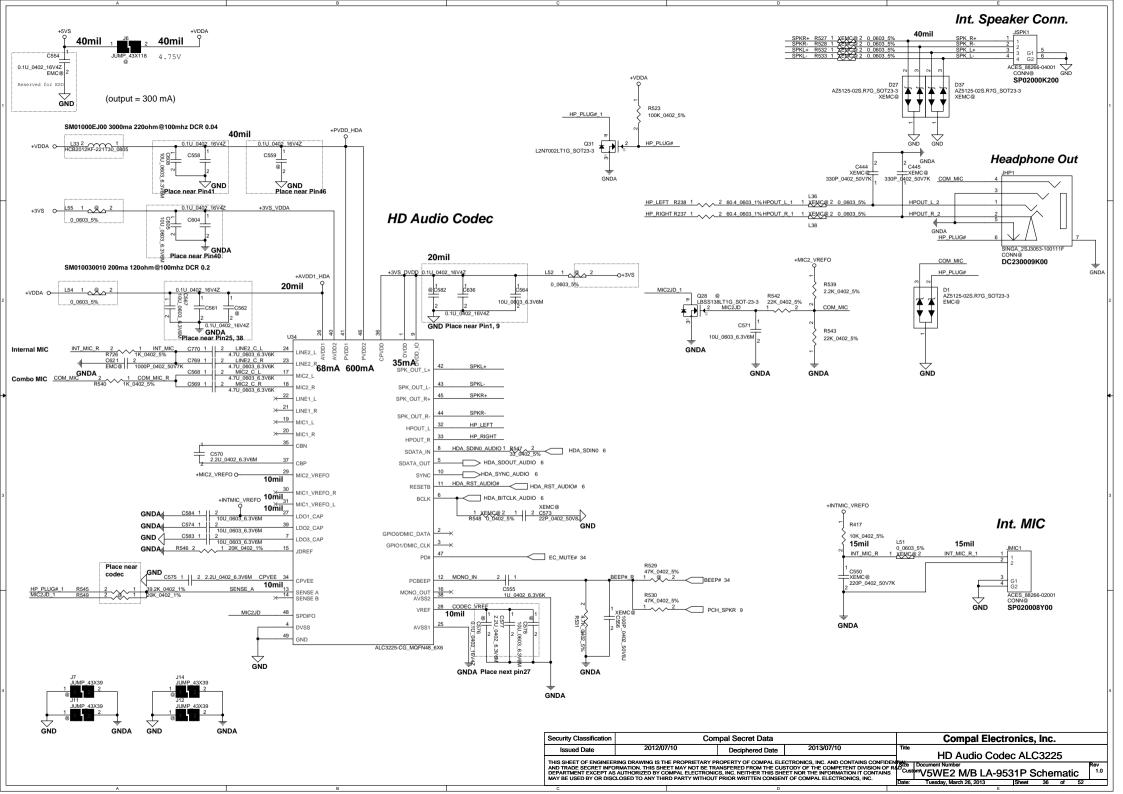
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Issued Date	2012/07/10	Deciphered Date	2013/07/10	Title	MINI CARD (WLAN)	
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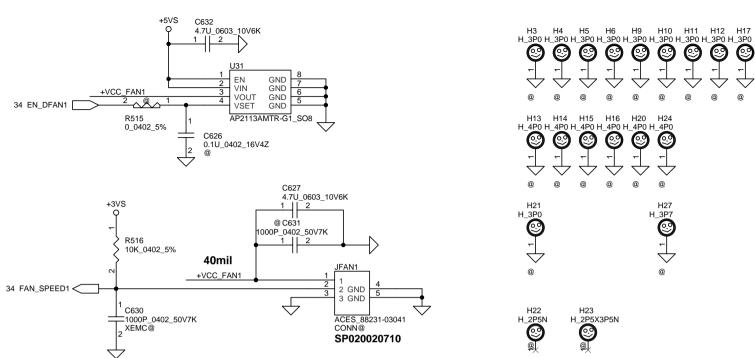


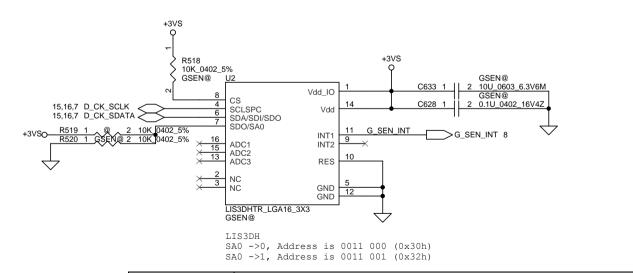






FAN1 Conn





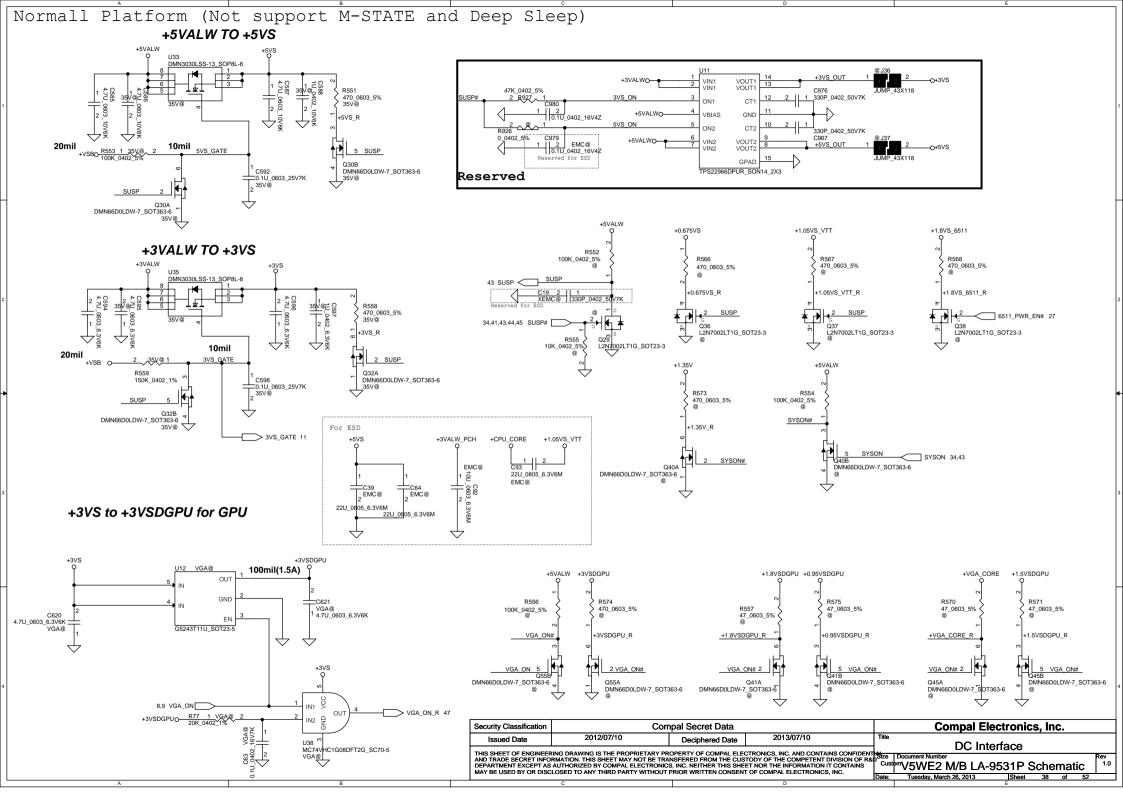
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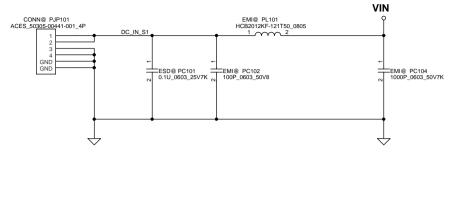
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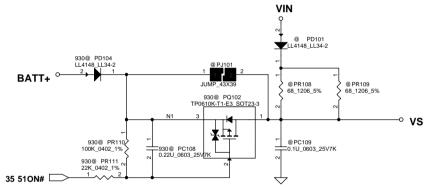
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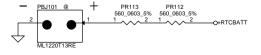
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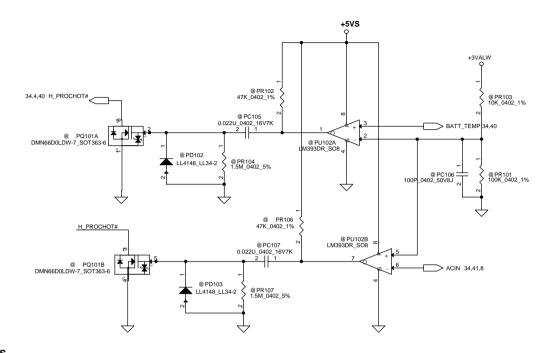




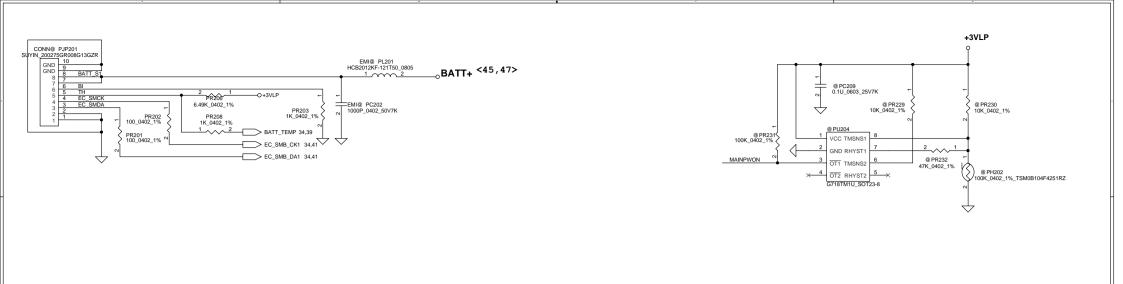


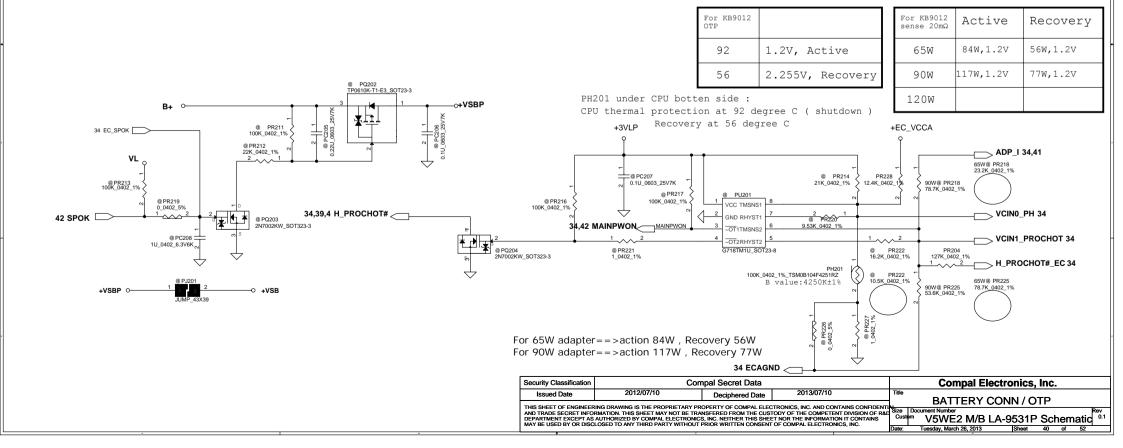


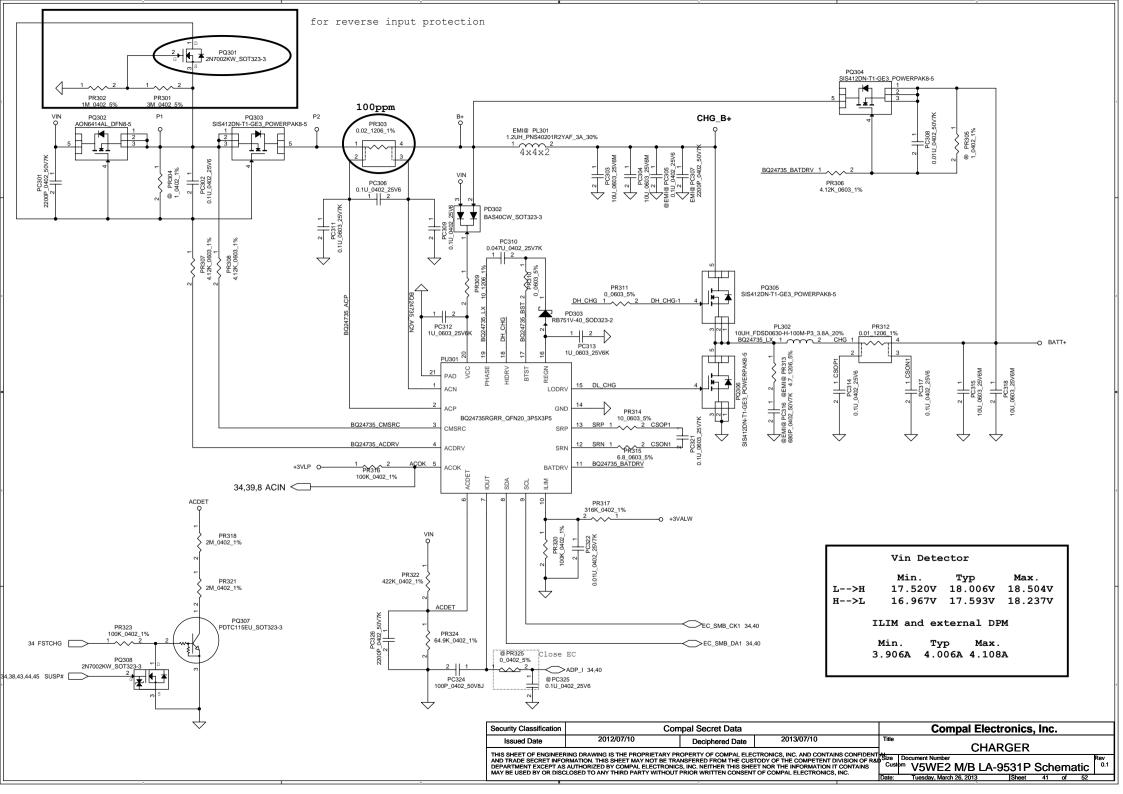


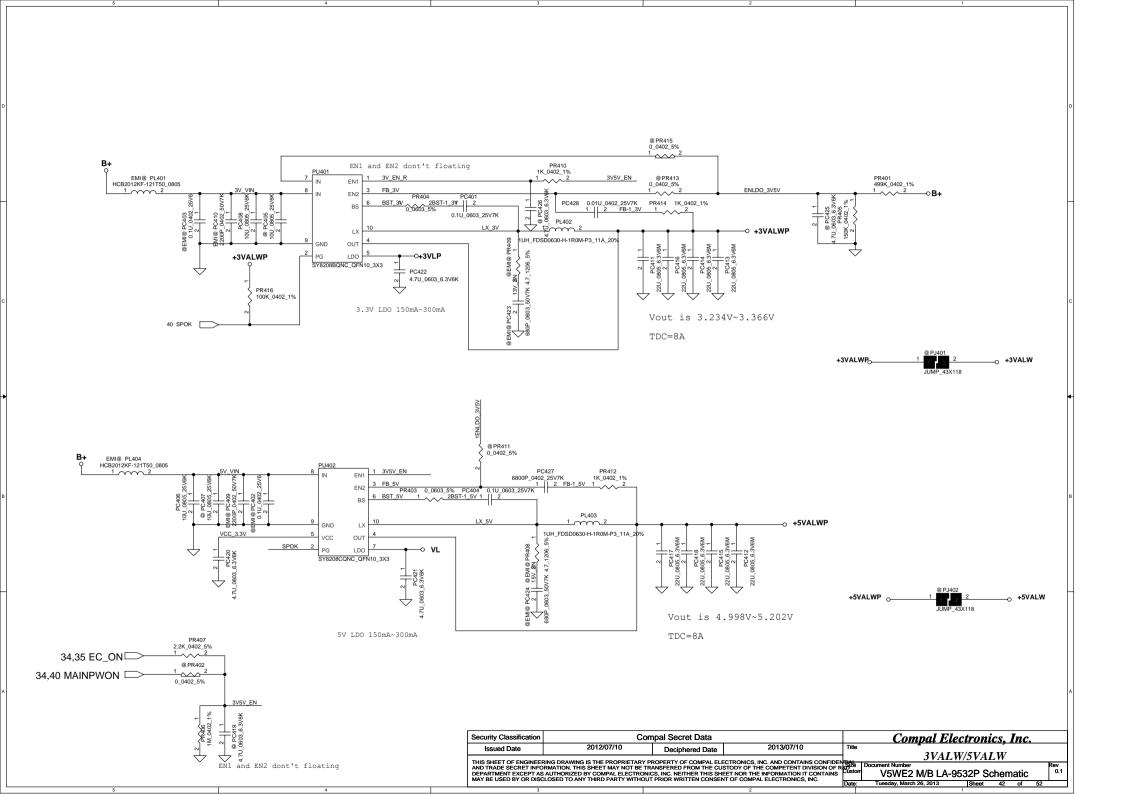


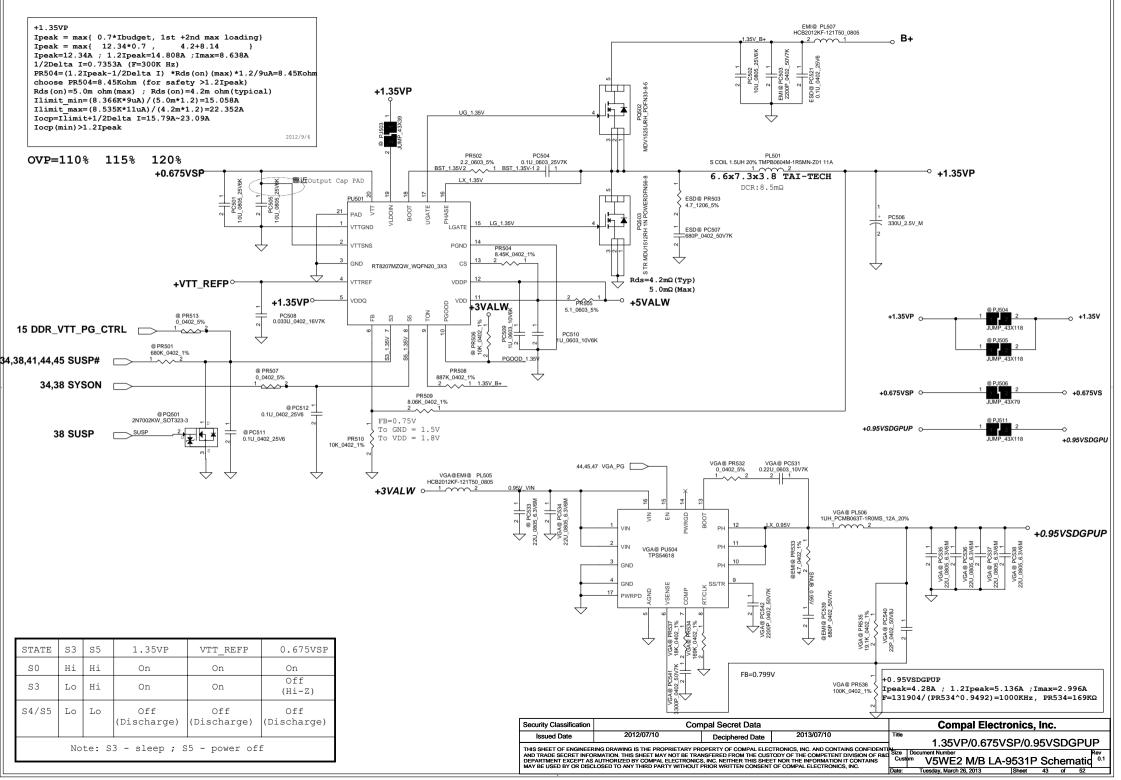
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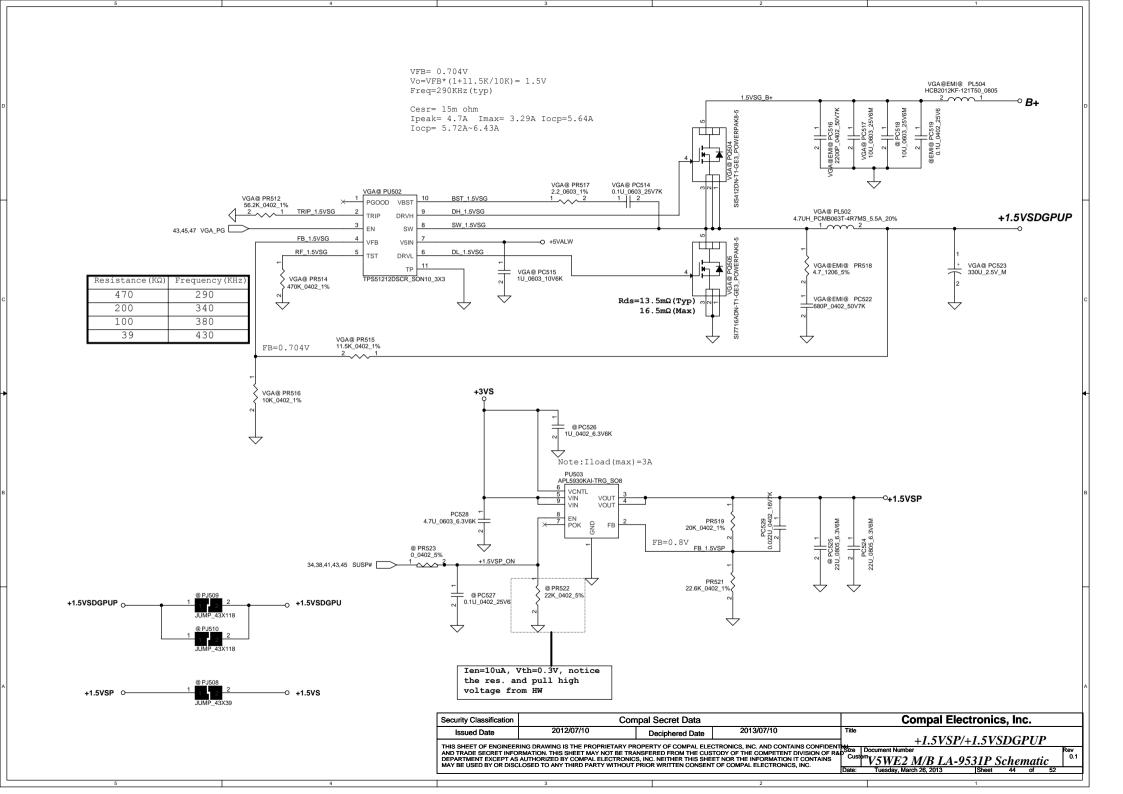


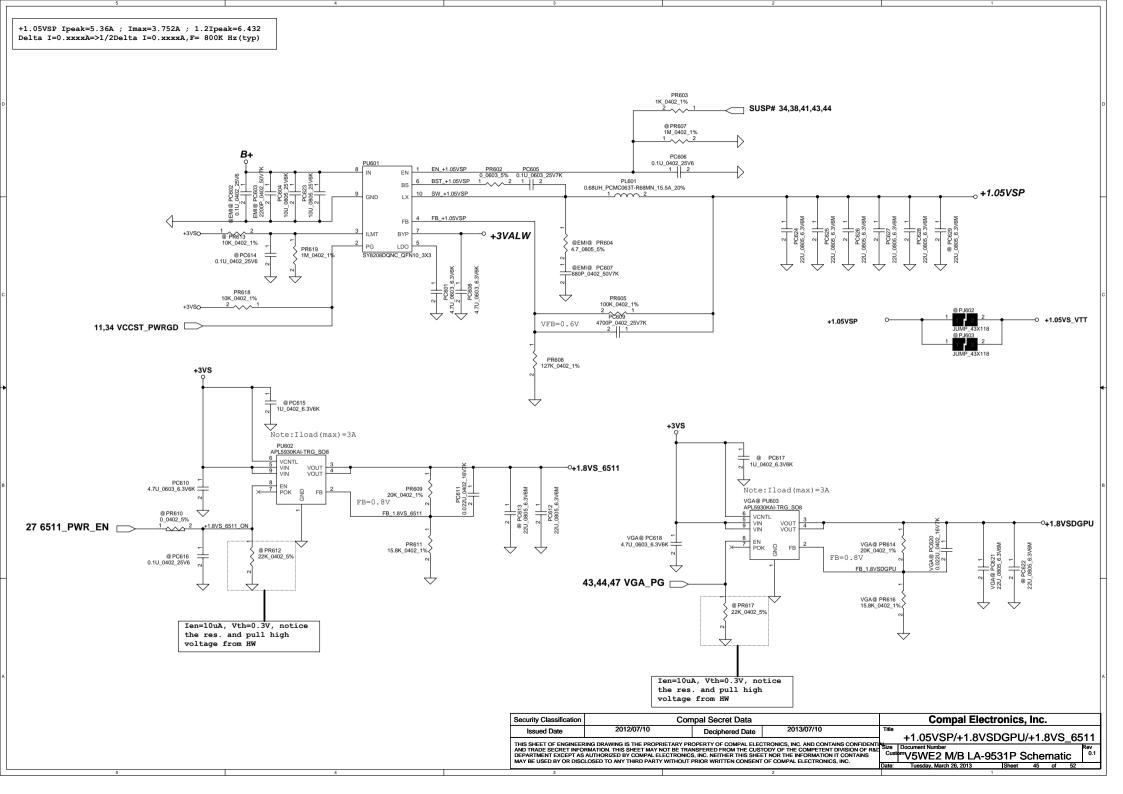


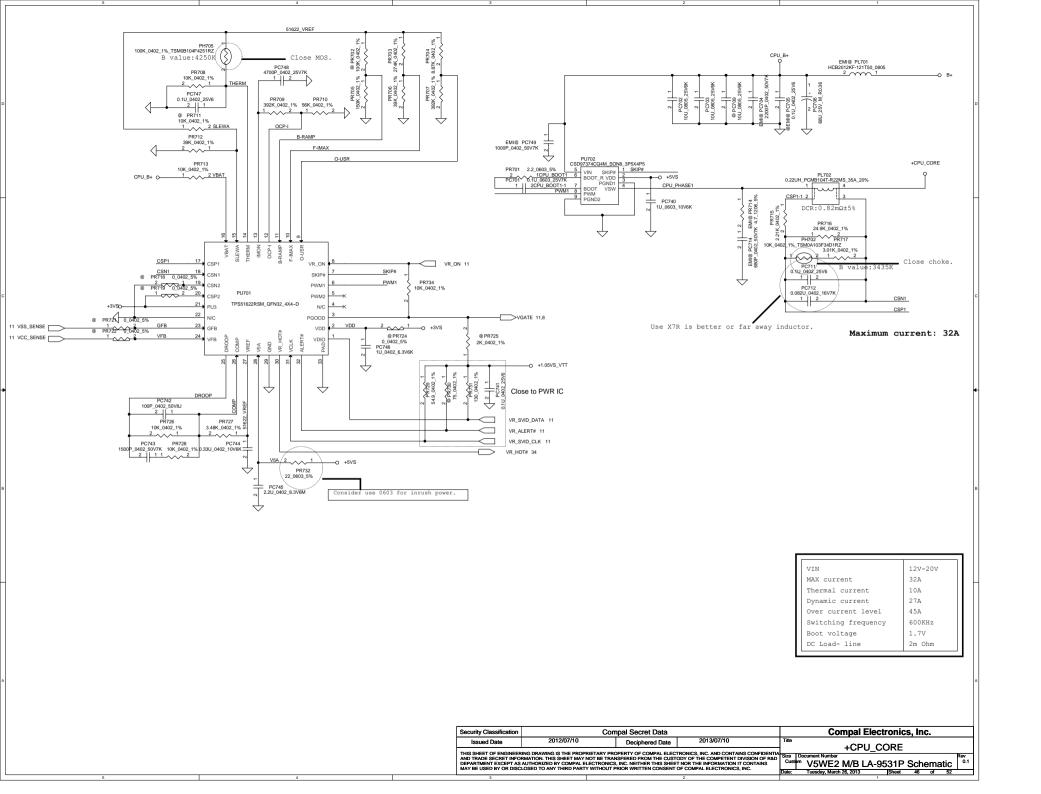


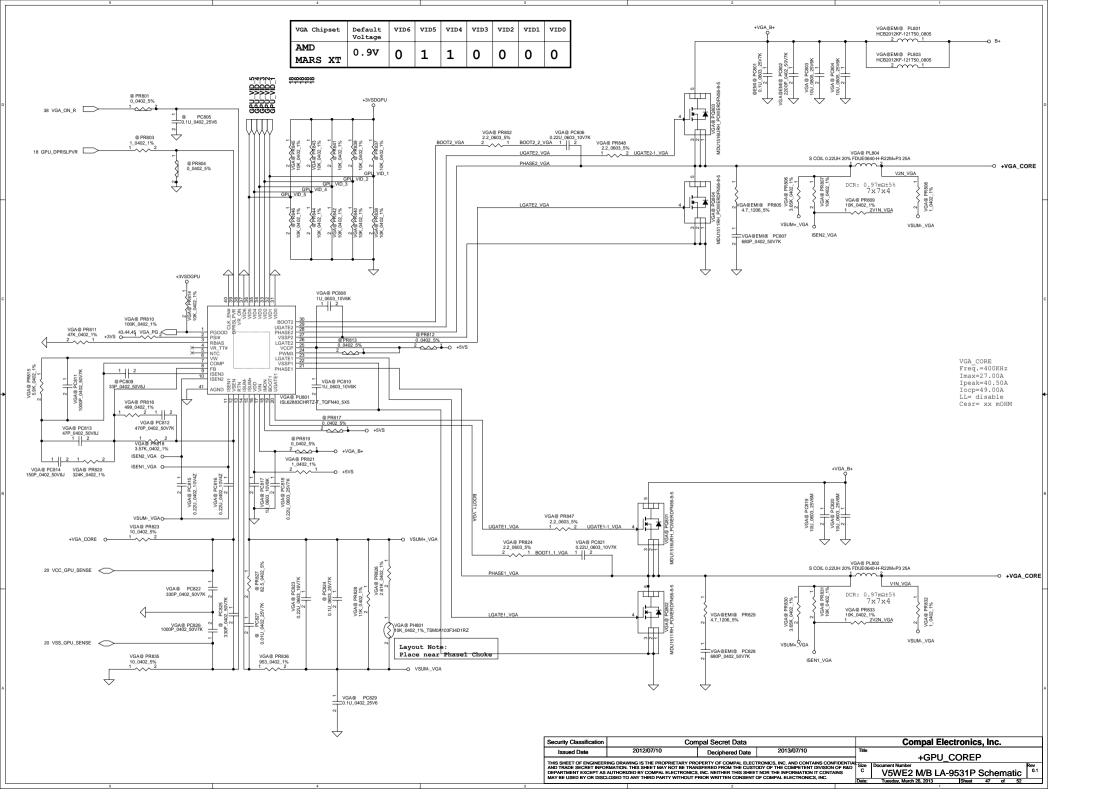


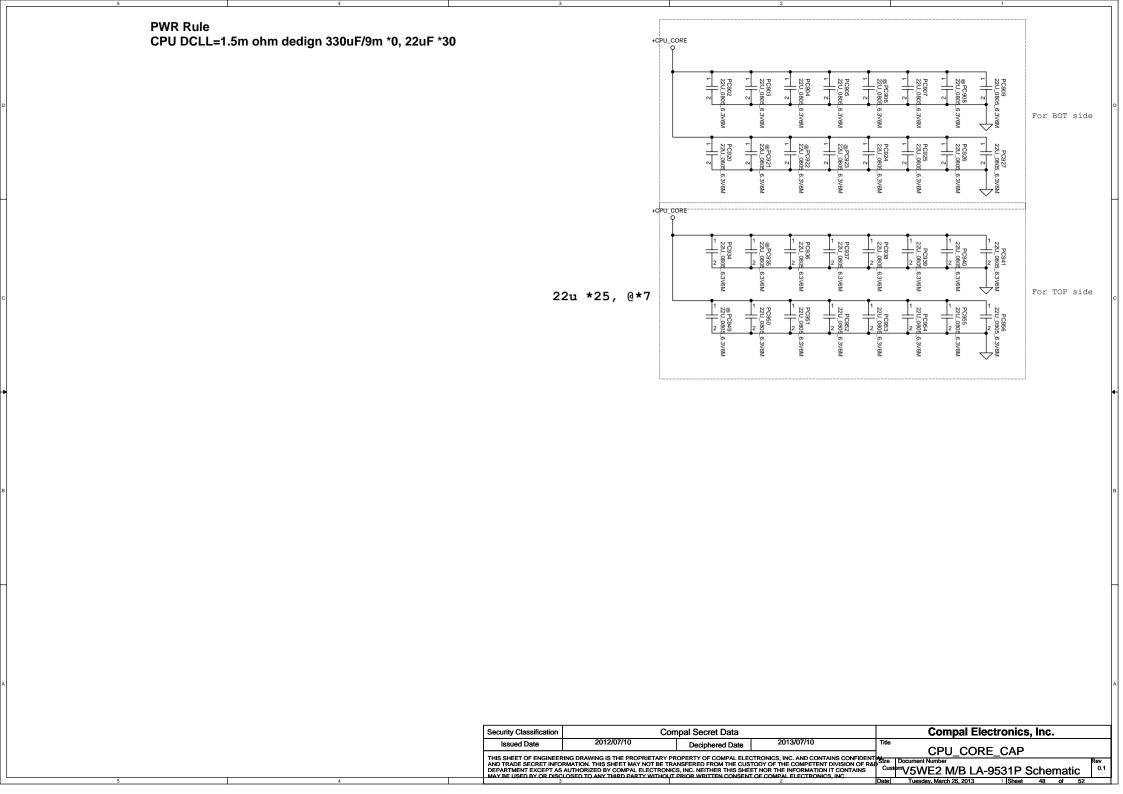


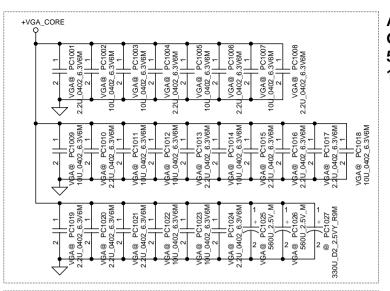




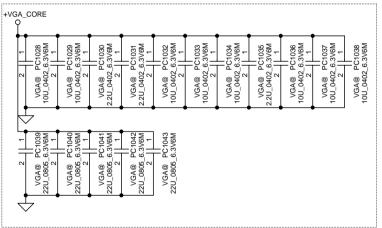








AMD MARS GPU_CORE 560uF*2+330uF*1 10uF*8+2.2uF*16



AMD MARS meet ripple 22uF*5+10uF*11

Version change list (P.I.R. List)

Page 1 of 2 for PWR

Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	Date	Phase
1	Tune VGA sequence	Tune VGA sequence		VGA	PR801 change to 20K Add PC805, PR814 Delete PR615, PC619, PR511, PC513, PR530, PR531, PC530	11/06	DVT
2	Module Design	Module Design change 3/5V solution		3/5V		11/13	DVT
3	3	Change RTC type to non-charge		39	Un-pop PR112, PR113	11/13	DVT
4		Check no need keep with HW		39	Delete PR112, PR113, PBJ101	11/20	ţ
5	EMI request	•		EMI	Add PR518, PC522, PR714, PC714, PR829, PC828, PR806, PC807, PC749 Change PR701 to 2.2	11/20	
6	EMI request	EMI confirm remove		EMI	Delete PL102, PC103, PC101, PL202, PC201 and PL703	11/26	DVT
7	Costdown			42	Change PL402, PL403 from 5x5x3 to 7x7x	3 12/13	DVT2
8		SY8208B/C update		42	Add PR411, PR413	12/22	DVT2
9	+1.05V ripple close	Adjust output voltage and add Cff		45	Add PC609 into 4700P	12/22	DVT2
	upper and mean too low				Change PR608 from 133K to 127K		
10	VGA_CORE can't disable	Modify VR_ON to VGA_ON_R net		47	Change PR801 from 20K to 0 Reserve PC805	01/04	DVT2
11		Improve CPU transient character		46	Change PR709 from 150K to 390K, PR732 from 10 to 22, PC745 from 1U to 2.2U, PC711 from 0.082U to 0.1U	01/09	DVT2
12		Improve CPU transient character		48	Unpop PC902	01/09	DVT2
13		Tune sequence		42	Change PC428 from 4700p to 10n,	02/04	¢
					PC427 from 0.047u to 6.8n		
14		0 ohm reduce			Change PR801, PR507, PR513, PR523 to R-page		
15		To meet MARS/AMD ripple SPEC		49	Add PC1028~PC1043	02/22	
16		Provide 3/5V PG signal to EC		42	Add PR416	02/22	\$
17	EMI request	Modify H-Gate resistor		47	Change PR847, PR848 from 0 to 2.2	02/25	¢
18	ESD request			39	Add PC101 into 0.1uF	02/26	·····
19	ESD request			43	Add PC521, PR503, PC507	02/26	
20		Use HW to control VCIN1 function		40	Add PR204	03/05	PVT
21	ME issue	Shrink component to reduce Z height			Change PC303, PC304, PC315, PC318, PC517, PC819, PC820 from 0805 to 0603	03/26	PVT2

___ Recovery at PVT phase

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1.Delete +3VALW to +3VALW PCH MOS Circuit: A --> B1 Change List 1. Page04, Move R25 to JXDP1.60 Page12, Delete C589,C414,R77,Q10,C590,C591 Update UI option component for CPU
2. Page6,8, Change EC SMI from GPI077 to GPI034
Delete R445
3. Page07, Change Y2 to X3G024000DC1H(SJ10000CS00) Page34, Delete U28.16 PCH_PWR_EN# off page 2.Page12, Unpop R210, Pop L3 and C22 for +1.05VS VTT high ripple 1.Page11, R169 change to @ 2.Page36, Mound R417 (Cancel AMIC@) 4. Page08, U17, U43, R310 change to @ 3.Page18, R898, R899, R409, D22 change BOM Structure to VGA@ 3.Page18, R898, R899, R409, D22 change BOM 4.Page34, R485, R483 change to 90120 R479, R478 change to 9400 5.Page35, C663, SW4, SW5 change to 90120 6.Page19, Delete R1035, X7601/X7603/X7604 7.Page17, R1006 change to VGA0 Mount R65 R310.1 change to +3VS 5. Change all 9326 to 9406
R161, D29, R564, U6, R569, C522, C523, C552, D36, Q39, R522,R586, R589, R607, R610, R624, R693, U41, U44, C516, C518, D28, R146, R158, R159, R160, R496, R499, R504, R507, R508, R511, R601, U28, U29
6. Pagell, R169 change to XDP@ Page28, Delete C606,C646,C607 Change R239 to R short 8. Page09, R306 add BOM structure UMA@ Page29, Delete C775,C776,C778,C781,C782 9.Page06, C153, C154 change to 15P_0402 10. Page18, C848, C849 change to 12P 0402 Page31, Delete C461,C462 7. Page12, add C414 and change PCH PWR EN to PCH PWR EN# 7. Page12, add C414 and change PCH PWR EN to PCH PWI delete Q33, R561, R563
8. Page16, delete R58, R298, R300, C163, R299, R302
9. Page17, Add option component (U51) for SUN_XT
10. Page19, Add R900, R901 with BOM structure @
11. Page24, delete R405, U20, R362, R401, C164
Change U8 to 65243AT11U (SA0000028Y10) Change R423 to R_short 11.Page07, C2, C3 change to 10P_0402 Page32, Delete C161 11294-----Change R308 to R short Page34, Change R495 to R_short Page36, Chagne L55,L54,L52 to R short 4.Page24, SWAP RP41.1,RP41.2 4.Page04, Add QDJC@ BOM Structure for U1 12. Page25, delete R367, D7, F1, D8, D19
13. Page26, change L47, L48 to BLM18AG121SN1D(SM010030010) 5.Page27, Change R123,R127 Pull high to +HDMI 5V OUT 1.Page18, Add D22 to prevent GPU ACIN leakage 1. Page22, Add X7603@ for VRAM 2Gb*4 HYN 128M16 Add X7604@ for VRAM 2Gb*8 HYN 128M16 14. Page27, Delete D31, F2, C450 1.Fage16, Add D22 to prevent GPT_ACIN Teakage 2.Broadcom recommend modify(Add component Function Field is 45.1) Page29, Add C803 0.1uF to U48.20(VDDO_CR), Page29, Add C74(BLM31PG601SN1) between Q6.1 and +3V_LAN Add C820 (1uF) to Q6.1 Page30, Add L75(BLM31PG601SN1) between Q9.1 and 15. Page28, Delete R781, D23, R782, R785, U49, C803 16. Page29, Delete R792 change T1 to GST5009-E (SP050006B10) 17. Page30, delete R414, C166 1. Page06, Add R937 for EC SCI# Path to GPIO34 2. Page09, RP28.5 connect to GPIO34 R438, Q20 change to @ +XDPWR_SDPWR_MSPWR 1. Page06, Delete chargeable RTC circuit Add C820 (1uF) to 09.1 3.Page18, Change L69 to R_Short Change ODD to SATA port1 Page 32, Modify ODD SATA netname to SATA port 1 . 4.Page20, Change L72 to BLM18AG121SN1D (the same to L71) 5.SW confirmed function 2. Page29, +1.2V_LAN_OUT add 680P for EMI 3. Page37, Modify H2 $\overline{1}$ from 2P5 to 3P0 4. Page38, Add 2 jump for power cousumption measure J36(+3VS), J37(+5VS) (ACPRESENT tp PCH no need) (EC BEEP no need) Page08, unpop R245,d21 20. Page33, Mount R503 Page36, unpop R529 6.Default EC SCI# to GPIO34 Change R506 to 8.2K Change R509 to R Short with BOM @ Page06, Pop R937 5. Delete XDP port and related circuit Delete R491, R493, D20 Page09, Unpop R66 Page04, Delete C63,C64,C96,C97,C98,R20,R21,R22,R23,R27~R31 21. Page34, add R535 (100K 0402) 7.Reserve DGPU HOLD RST# direct to PLTRST_VGA# path Page08, Add R405 Oohm connect DGPU HOLD RST# and PLTRST_VGA# Delete R3, R86, R87, R88, R89, R90, R91, R4, C92, C93 Mount R632 Mount R632
21. Page35, L51 change to BLM18AG121SN1D(SM010030010)
Change JMIC1 to ACES 88266-02001(SP020008Y00)
Delete R143, R668, Rī62, R181, C719, R671 Delete R5,R14,R15,R16,R7,R19,R25,C35,JXDP1 8.Page35, Chagne R702 to 680ohm (ME confirm) 0.Fage37, Delete SWI (debug) for Layout convenience 10.Page24, Change L6 to (4.7uH SH00000GSO) same as Q5WV8 11.Page29, Change RE22 to R768,R769,R770.R771 for SD 3.0 EMI Page07, Delete R66,R67 6. ESD DVT Modify: Page08, Delete C39 23. Page37, delete R424, C169
Change U12 to G5243AT11U(SA000028Y10) Page24, Delete D6 24. Page43, SW1 change BOM Structure to @ Page28, Delete D7, D18 1.Page24, Change U50.11 connect from L6.2 to L6.1 Page30, Delete D38 2.Page34, Change R502 from R_short to 940@ 0.hm 3.Page36, Change R237,R238 to 60 Ohm(Codec vendor recommend) Page33, Delete D16 1. Modify BOM Structure/Function Field for EMC@(45.1) Page35, Delete D25, D30, D34 Page06, RP14 Page07, RP19, R390 4.Page09, Add R67 for EC SCI# -> GPIO 10 option Page36, Delete D20, D30, D34
Page36, Delete D26, R544, C572
Page37, Delete ESD TP JUMPs:
J10, J20, J17, J21, J16, J19, J18
J22, J24, J28, J25, J29, J23, J27 Page24, L11
Page25, R368, R369, R370, R371, R372, R373, R374, R375 1.Page36, Delete D26 (ESD Confirm) .EMI part Schematics modify (EMI confirm1123) Page27, L42, L45, L46,R175, R180 Page26, Change R368,R369,R370,R371,R372,R373,R374,R375 to 0403 J26, J30, J31, J33, J32, J34, J35 Page29, R897, C814, D39 Page29, C786 change to EMC@ Page28, Change R175,R180 to 0603 R short Fage29, key7, Cs14, D39
Page32, L24, L25, R458, R461
Page35, R527, R528, R532, R533, L36, L38, D1, C62
2. Modify BOM Structure/Function Field for XEMC@ (45.1)
Page04, C63, C64, C96, C97, C98, C94, C95, C60, C92, C93, C35
Page07, R104, C152, R402, C453 Page 04, Add C96 to DIMM_DRAMRST# Page 33, C487 change to EMC@ and 0.1uf Page36, Change L36,L38,L51,R527,R528,R532,R533 to 0603 R_short Page32, Delete C408,C398 Page33, Delete C406,0590 Page33, Delete R453,R455,R456,R457 3.Page38, Change 3/5 VS circut BOM Structer to 35V@ 4.Page32, Modfiy JHDD1 to LTCX004LGA0 (S H-CONN CCM Delete D4
Page26, C378 change to EMC@
C387 change to EMC@ Page08, C39 Page24, C528, C549, C364, C365, D6 C127043HR022M27FZR 22P H3.05 HDD) 1. Page06, Add a nochargeable RTC battery. Modfiy JODD1 to LTCX004HZ00 (S H-CONN SANTA 20190X-X 13P Page15, Add R191 for DDR VTT_PG_CTRL pull high +5VS option.
 Add page24, Reserve eDP to LVDS translator (RTD2132R) Page25, D2, L13, L14, L15, L16 Page28, C792, C786 Page28, C792, C786
Page29, R26, C26, C806, C807, C808, C809, JP1, JP2, D38
Page31, C408, C398
Page32, D15, D16, D4, C487, R453, R455, R456, R457, L26
Page33, R477, C501, R513, C520, C506, C507, C511
Page34, C551, C553, D25, D30, D34 Add bom structure TLE(translate) and EDPE(eDP mode)
4. Page25, Add R947 for ENVDD option.
Add connect TL_INVT_PW to INVTPWM
Add connect RTD2132R TL_HED to EDP_HPD Modify JLVDS1 pin net name fo Co-Lay eDP & LVDS Page35, R548, C573, R671, C719, C556, C550, C444, C445, D27, D37, D26, R544, C572 3. Modify Function Field to 45.1 only (BOM Structure is same as before) Page04, R27, R28, R29, R30, R31 Page07, RP20 Page33, R160 Page35, R143, L51 4. Display BOM structure and Value of U1 (CPU) 5. Display BOM structure of R0402 OOHM-NEW and R0603 OOHM-NEW (R Short Pad show BOM Structure @) 6. Page08, Update note of GPI066

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B1 --> B2 Change List

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0114-----
 1.Page03, Add U1 with QDJA@
 2.Page30, R897 change to SM01000LU00
 3.Page24, L63,L73 change to SM01000EJ00
 4.Page25, L11 change to SM01000EJ00
5.Page36, L33 change to SM01000EJ00
6.Page31, U9, C165 with IOAC@
0110-----
1.Page32, Delete R312,R313,R314,R315
Add C392,C393,C391,C394 with EA500
 2.Page27, Add C35
 3.Page38, Delete Q45,R570,R571
 0108-----
 1. Page33, R458, R461 change to R0402_00HM-NEW
Add JFP1

2. Page26, Delete L13, L14, L15, L16

3. Page29, Delete C792, C99
4. Page31, Delete J4
5. Page10,25 change Touch screen port from USB port 5 to port6.
 6. Page25,34 change net name of TS INT to TS EN
 7. Page10 add USB port 5 for Finger Print
 8. Page38, Add C19
8. Page38, Add C19

9. Page26, Add C396, C398

10.Page36, Mount C554

11.Page38, Mount C979

12.Page35, Reserved SW6,SW7,SW8,SW9
 13.Page32, Add C534, C535, C536, C537 for JHDD2 with BA510
               change C391, C392, C393, C394 to R312, R313, R314, R315
 Update Power schematics
 0107-----
0107------
1. Page06, R937 change to R0402 00HM-NEW
R75 change to R0603_0OHM-NEW
2. Page07, R108 change to 15_0402_5% with 1R0M0
RP19 change to 15_0804_BP4R_5% with 1R0M0
Add R105, R106 with 1R0M0 for PCH_SPI_IO2_1, PCH_SPI_IO3_1
Change R102, R103, R109, U7, C67, PR20 to 2R0M0
3. Page08, R62, R65 change to 0402_0OHM-NEW
4. Page10, Change Touch Screen USB port frum Port3 to Port5.
R155 change to R0603_00HM-NEW
5. Page24, Change Q53 to @
6. Page25, R947,R363,R949 change to R0402_00HM-NEW
                Add C376,C377,C388,C389 with TL0
               Add R414, R426
Add R424, R425 with @
7. Page27, R80 change to R0603_00HM-NEW L48 change to R0603_00HM-NEW
8. Page29, C99 change to XEMC®
R774 change to SEMC®
9. Page32, R49, R593 change to R0805_OOHM-NEW
9. Page34, R236 change to R0805_OOHM-NEW
 10. Page38, R926 change to R0402 00HM-NEW
 1.Page35, R698,R701 change to 680 ohm
R702 change to 499 ohm
2.Page18, Un-mount C847
3.Page38, Add U38, R77, C63
 Update Power Schematics
 1. Page25, Add USB20_P3/N3 on JLVDS1.35/36
                Add R81
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B2 --> C Change List

306	
	Mount R410, R411 Change R240, R241 with @
2204	Change R418 to 4.7K
l.Page20, 2.Page25, 3.Page33,	Mount C872, C873, C874, C889, C917, C918, C919 change C371,C372, C369, C370 with EDP@ Change L24, L25 to SM070001E00
2.Page12, 3.Page34,	Add D25 Reserved D26
2.Page32,	Del R766 change JDB1 to E-T_1001K-F50C-05R_50P-S
Modify fo:	
	Mount C13,C14 (10U 0603)
	Change C40 to 10U_0603 Mount C31 (1U_0402)
-	Mount C117 (10U_0603) Add C161 10U_0603
-	Mount C483 with 0.1U Reserved D3 with XEMC@
Jpdate po	Add C39, C64,C92,C93 22U_0805 wer schematics
l.Page12,	
-	Mount R204,R241, R407,R408 Change R412,R413 with @
	Add R312 with @ Del R590 (Add offpage for H_PROCHOT#_EC)
	Del R505 wer Schematics
	R898, R899 change to R0402 OOHM-NEW
	Add TS@ for R81, R414, R426
-	34,37 G_SEN_INT connecto to PCH_GPIO80 Change U2.4, U2.6 to D_CK_SCLK/D_CK_SDATA
	Reserved C815 Add C1024, C1025, C1026, C1023, C1027, C1028, C1029, C1030 with 1280
	Add C1031, C1032, C1033, C1034, C1038, C1036, C1037, C1035 with VGA(
5.Page38,	Reserved R556, R574, Q55, R557, R575, Q41, R570, R571, Q45
L.Page06,	Update Y1 CIS Symbol
- '	Add D23, C151
	Change R446, D32, C168 to @
	Change C823, C827, U52, R798 with @
	Add R781, C792 Add R782 and Mount C822
	Change R506 to 33K

C --> Pre-MP Change List

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